

EE 330

Lecture 29

Bipolar Processes

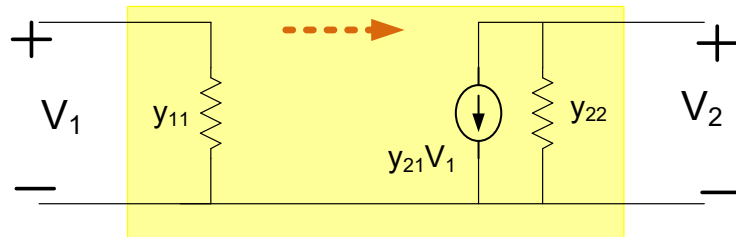
- Device Sizes
- Parasitic Devices
 - JFET
 - Thyristors

Thyristors

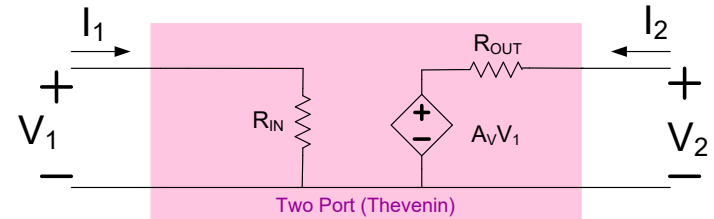
- SCR – Basic operation

Two-port representation of amplifiers

- Amplifier often **unilateral** (signal propagates in only one direction: $y_{12}=0$)
- One terminal is often common
- “Amplifier” parameters often used

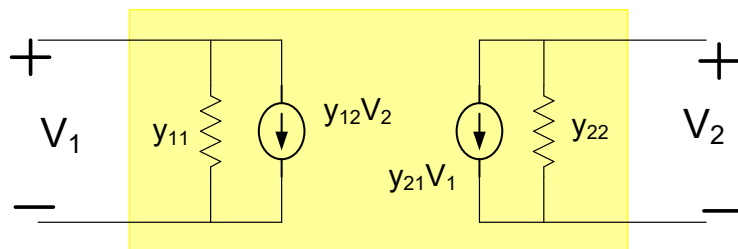


y parameters

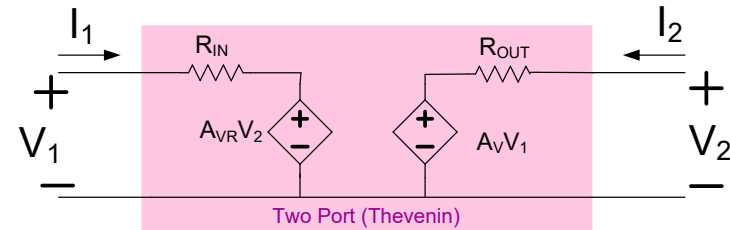


Amplifier parameters

-
- Amplifier parameters can also be used if not **unilateral**
 - One terminal is often common

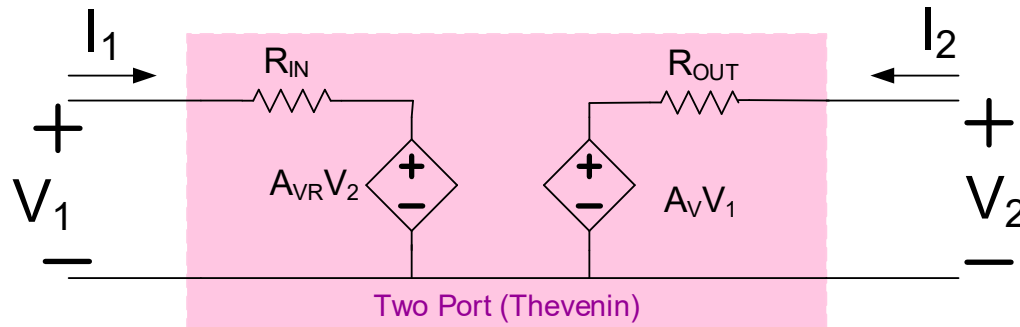


y parameters



Amplifier parameters

Relationship with Dependent Sources ?



Dependent sources from EE 201

Voltage
Amplifier

$$v_s = \mu v_x$$

Voltage Dependent
Voltage Source

$$I_s = \alpha v_x$$

Voltage Dependent
Current Source

Transconductance
Amplifier

Transresistance
Amplifier

$$v_s = \rho I_x$$

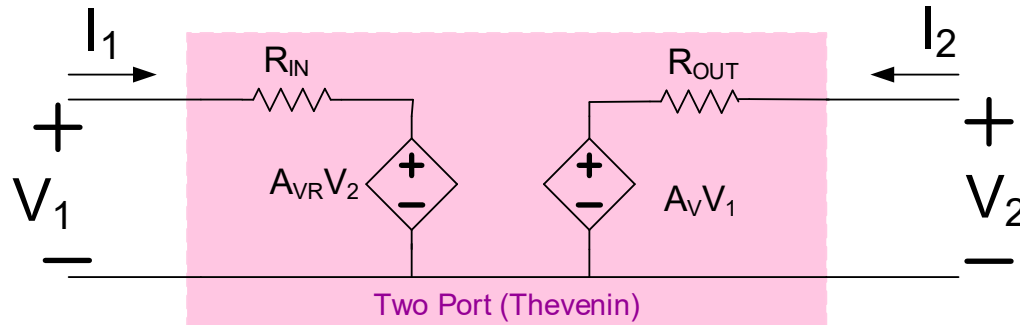
Current Dependent
Voltage Source

$$I_s = \beta I_x$$

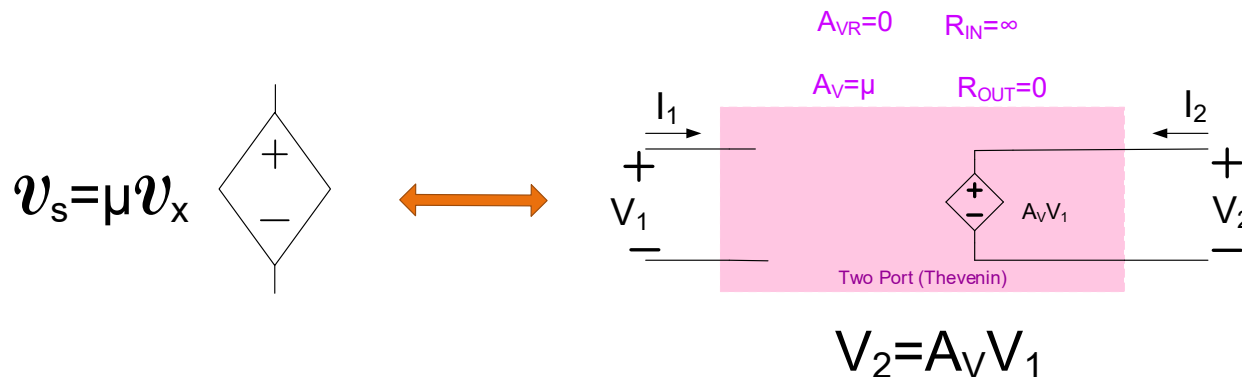
Current Dependent
Current Source

Current
Amplifier

Relationship with Dependent Sources ?

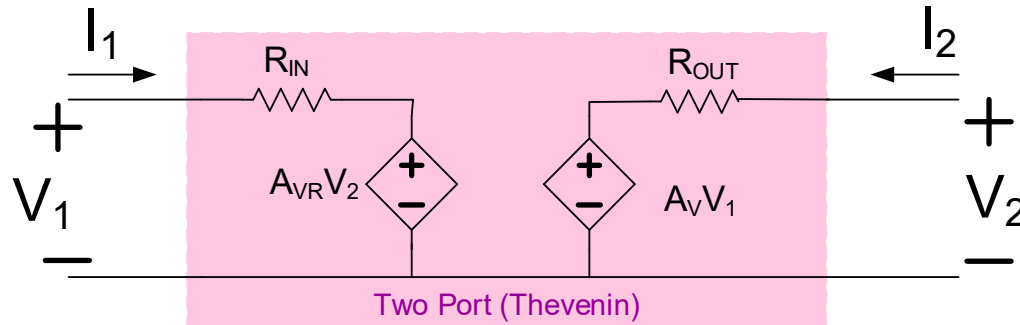


It follows that

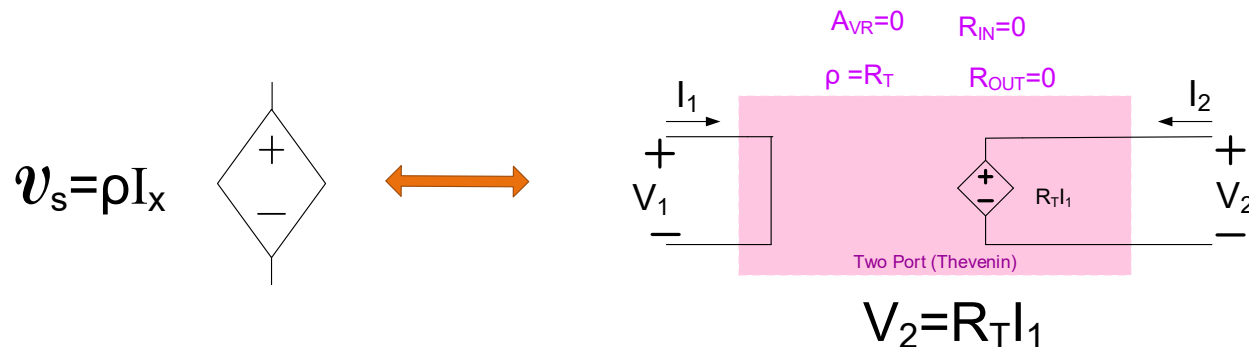


Voltage dependent voltage source is a unilateral floating two-port voltage amplifier with $R_{IN} = \infty$ and $R_{OUT} = 0$

Relationship with Dependent Sources ?

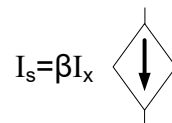
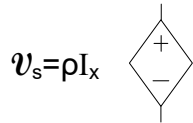
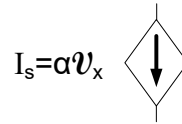
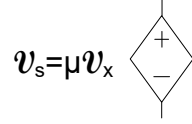


It follows that



Current dependent voltage source is a unilateral floating two-port transresistance amplifier with $R_{IN}=0$ and $R_{OUT}=0$

Dependent Sources



Dependent sources are unilateral two-port amplifiers with ideal input and output impedances

Dependent sources do not exist as basic circuit elements but amplifiers can be designed to perform approximately like a dependent source

- Practical dependent sources typically are not floating on input or output
- One terminal is usually grounded
- Input and output impedances of realistic structures are usually not ideal

Why were “dependent sources” introduced as basic circuit elements instead of two-port amplifiers in the basic circuits courses???

Why was the concept of “dependent sources” not discussed in the basic electronics courses???

Topical Coverage Change

Will have several additional lectures on amplifier structures but will temporarily suspend discussion of amplifiers to consider Thyristors

This is being done to get ready for the Thyristor laboratory experiments

Outline

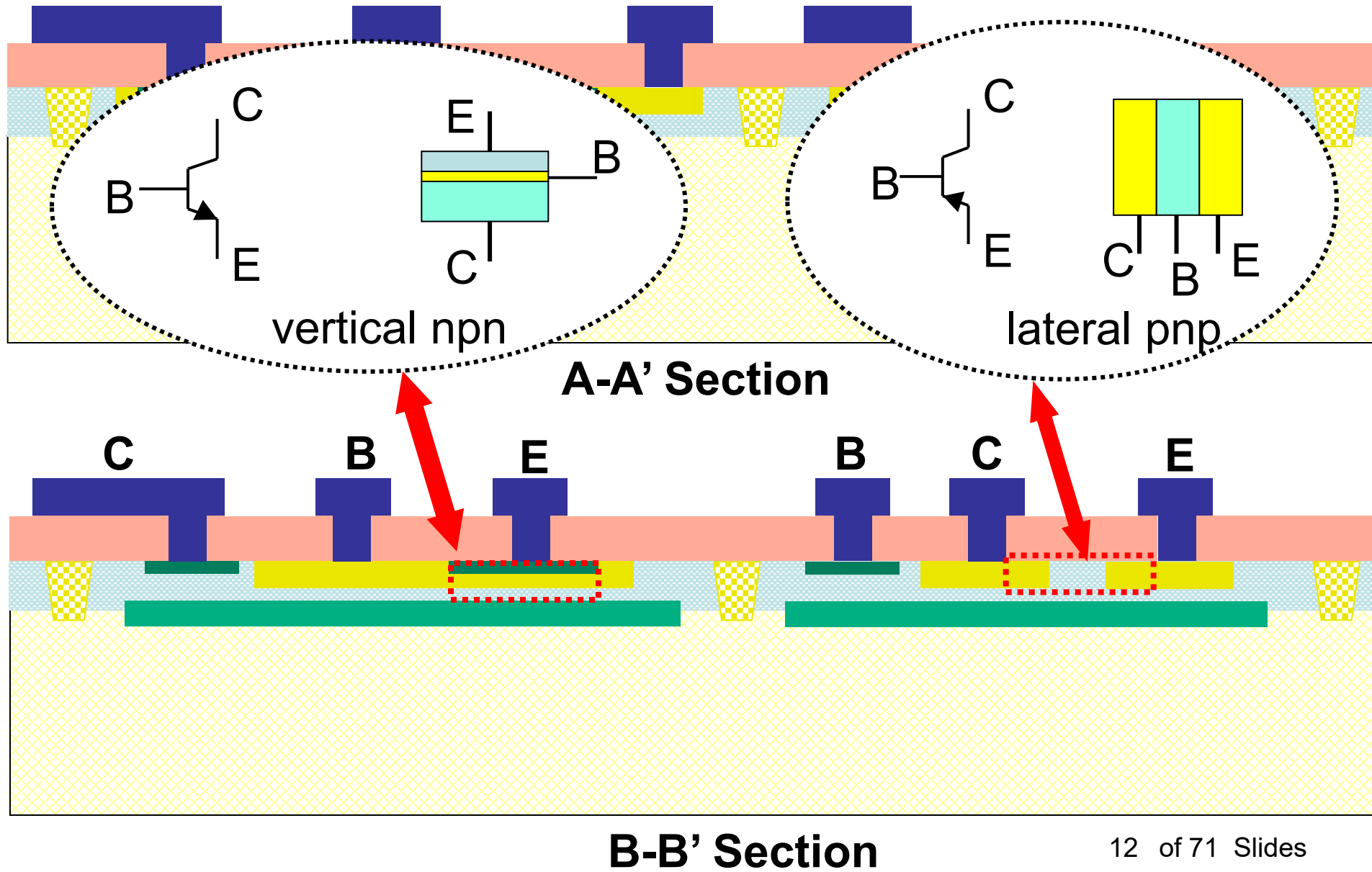
Bipolar Processes

- 
- Parasitic Devices in CMOS Processes
 - JFET
 - Other Junction Devices

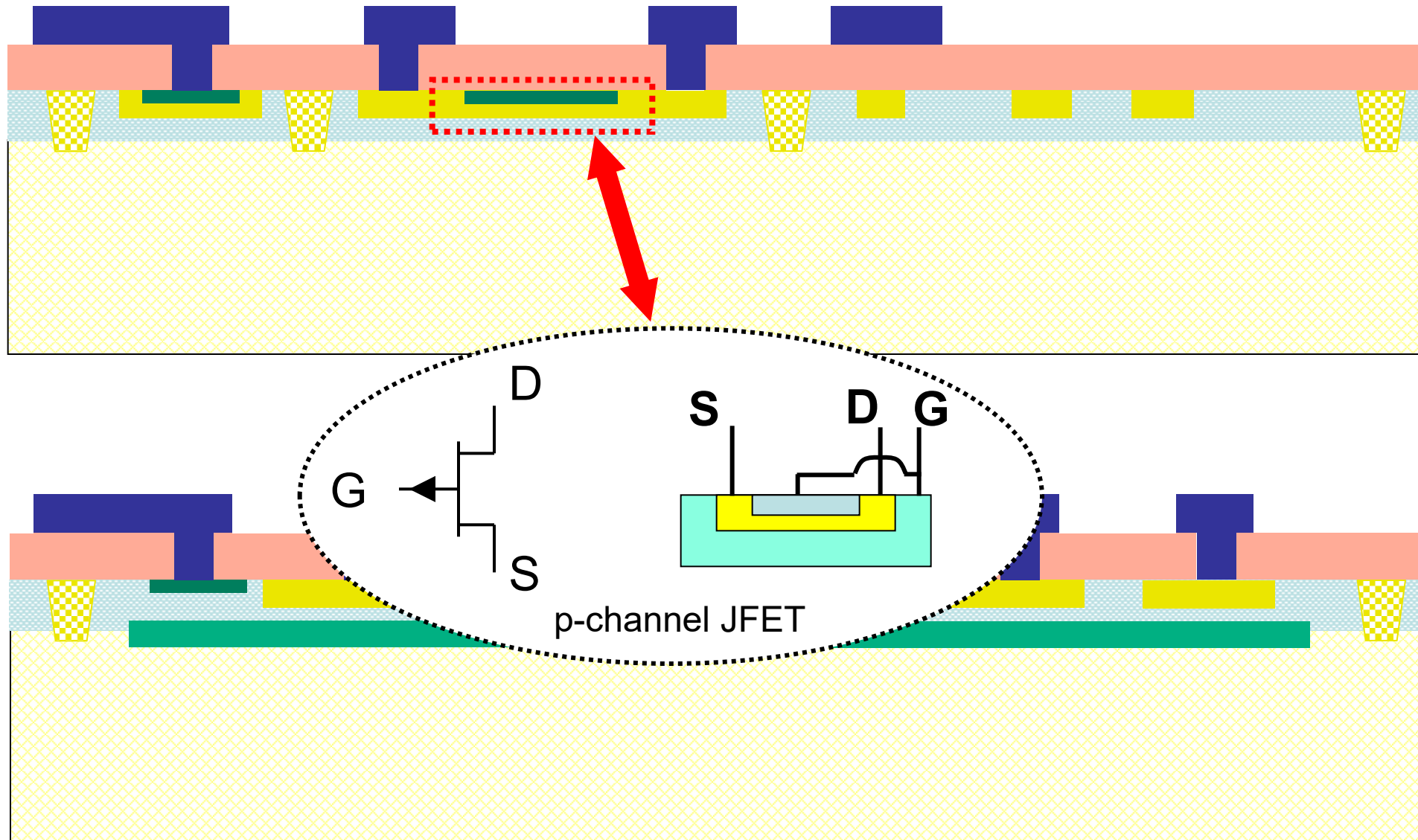
Special Bipolar Processes

- Thyristors
SCR
TRIAC

Review from a Previous Lecture

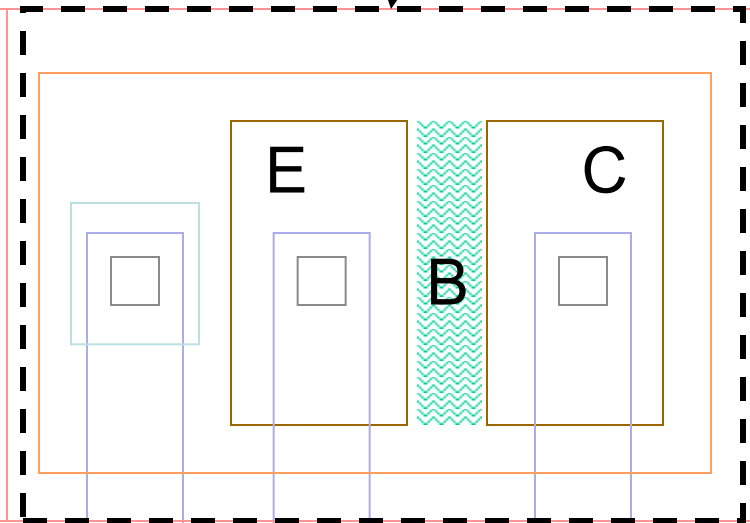
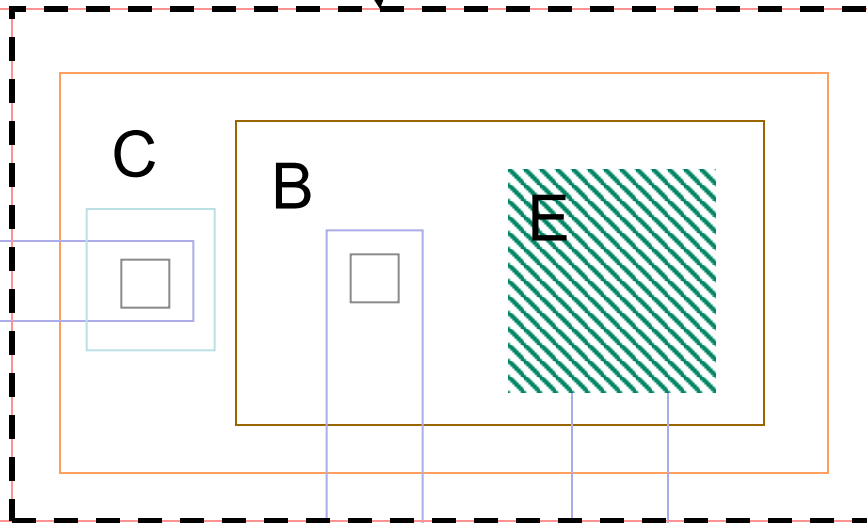
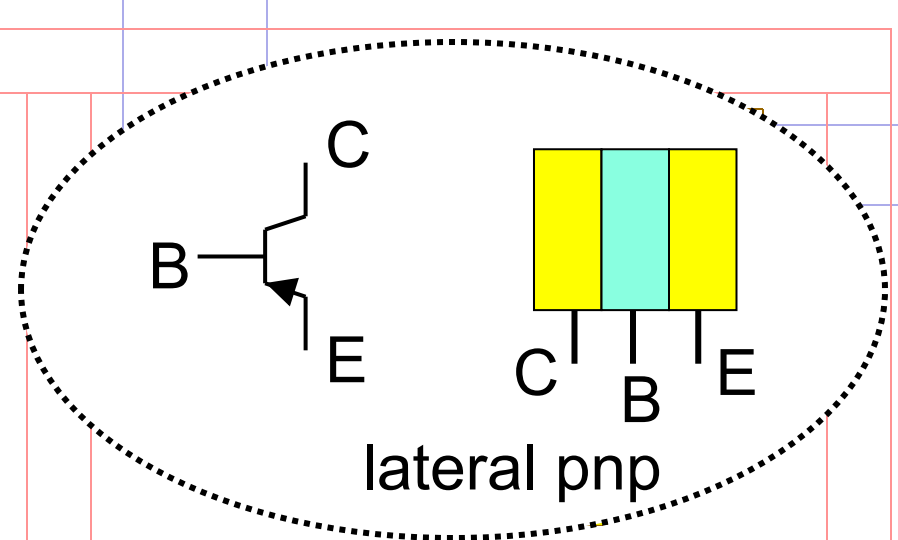
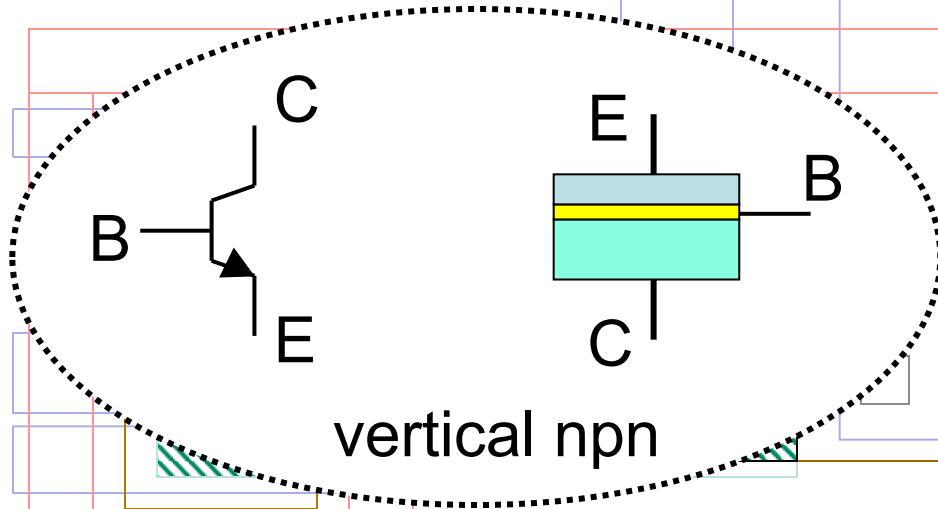


Review from a Previous Lecture

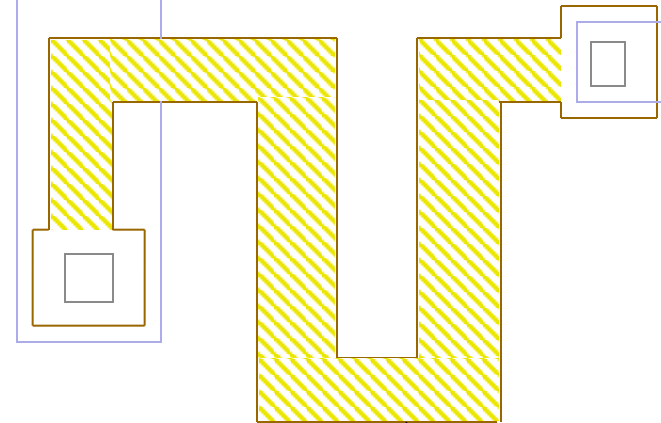
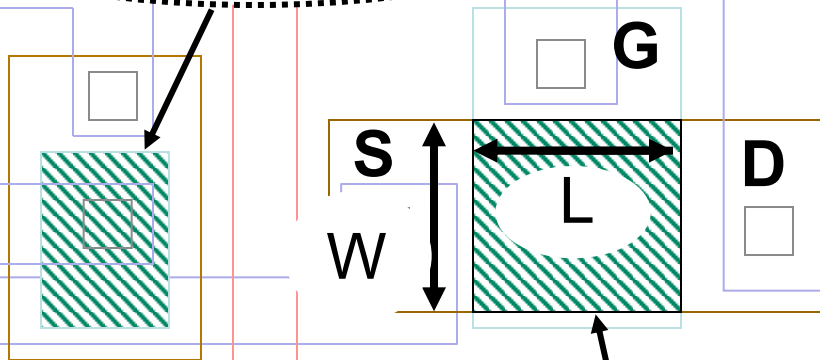


B-B' Section

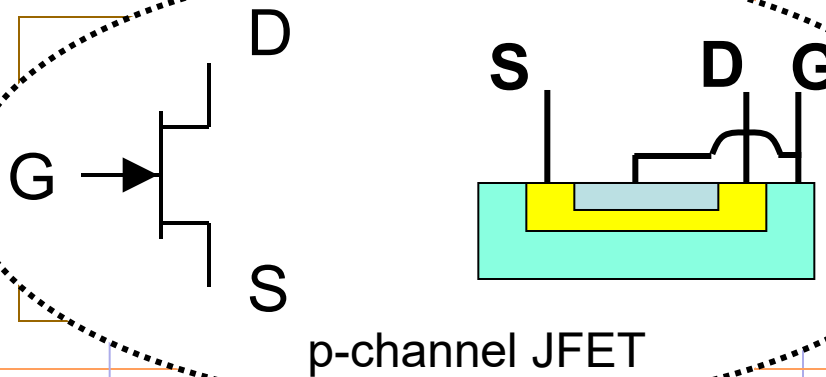
Review from a Previous Lecture



Diode (capacitor)



Resistor



Will consider next the JFET but first some additional information about MOS Devices

Enhancement and Depletion MOS Devices

- Enhancement Mode n-channel devices

$$V_T > 0$$

- Enhancement Mode p-channel devices

$$V_T < 0$$

- Depletion Mode n-channel devices

$$V_T < 0$$

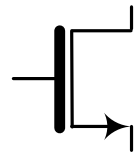
- Depletion Mode p-channel devices

$$V_T > 0$$

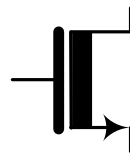
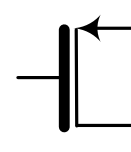
Enhancement and Depletion MOS Devices

n-channel

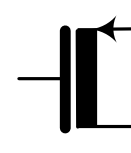
p-channel



Enhancement



Depletion



- Depletion mode devices require only one additional mask step
- Older n-mos and p-mos processes usually had a depletion device and an enhancement device
- Depletion devices usually not available in CMOS because applications usually do not justify the small increased costs of processing
- The threshold voltage of either n-channel or p-channel devices is adjusted to a desired value by doing a channel implant before gate oxide is applied

Outline

Bipolar Processes

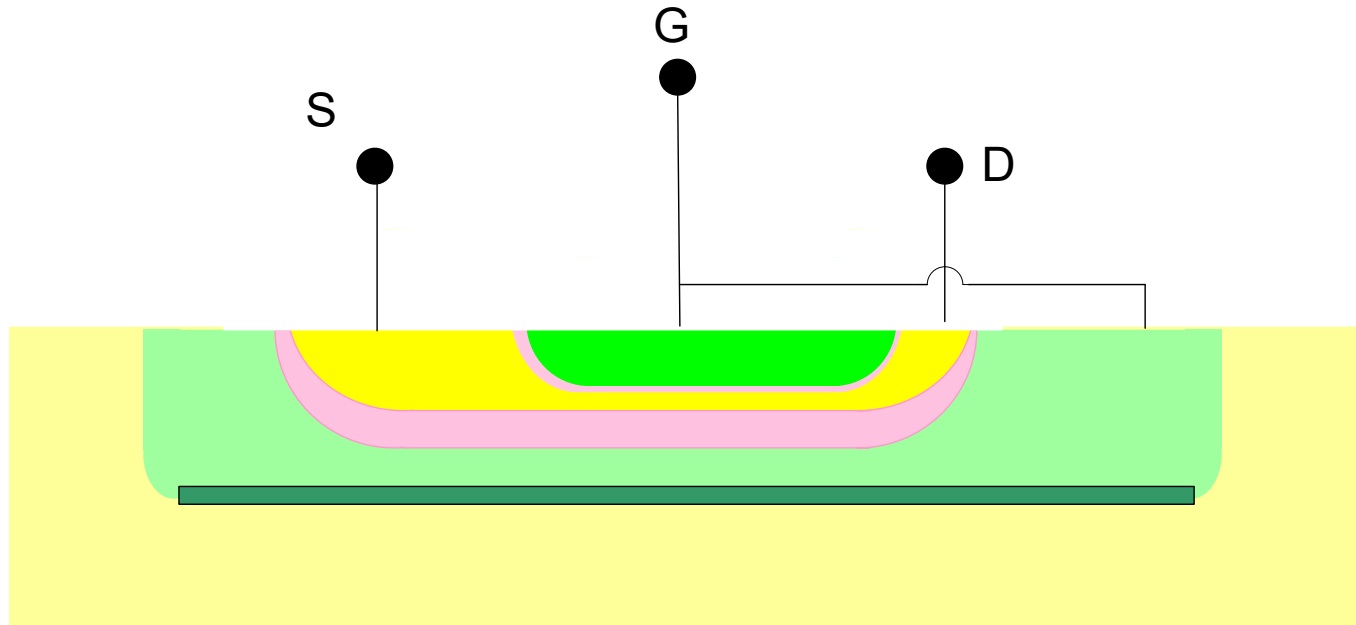
- Parasitic Devices in CMOS Processes
-  • JFET
- Other Junction Devices

Special Bipolar Processes

- Thyristors
SCR
TRIAC

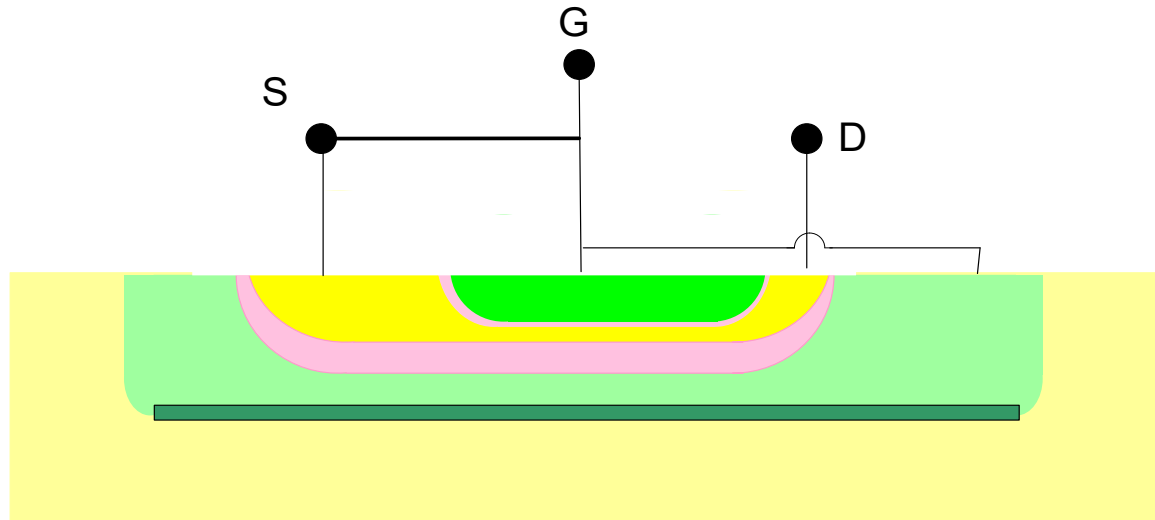
The JFET

(Parasitic p-channel device in basic bipolar process)



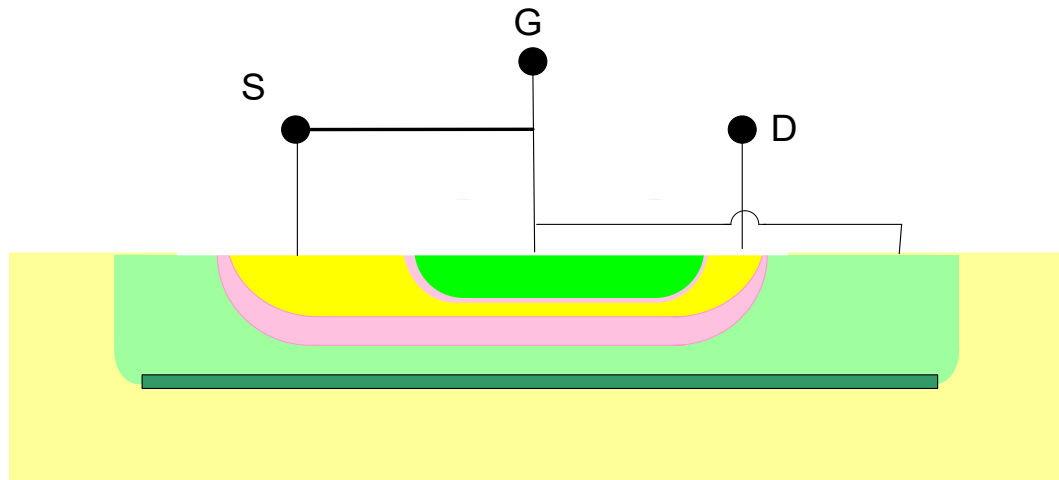
- Gate is both above and below channel
- With no bias, channel exists between D and S

The JFET

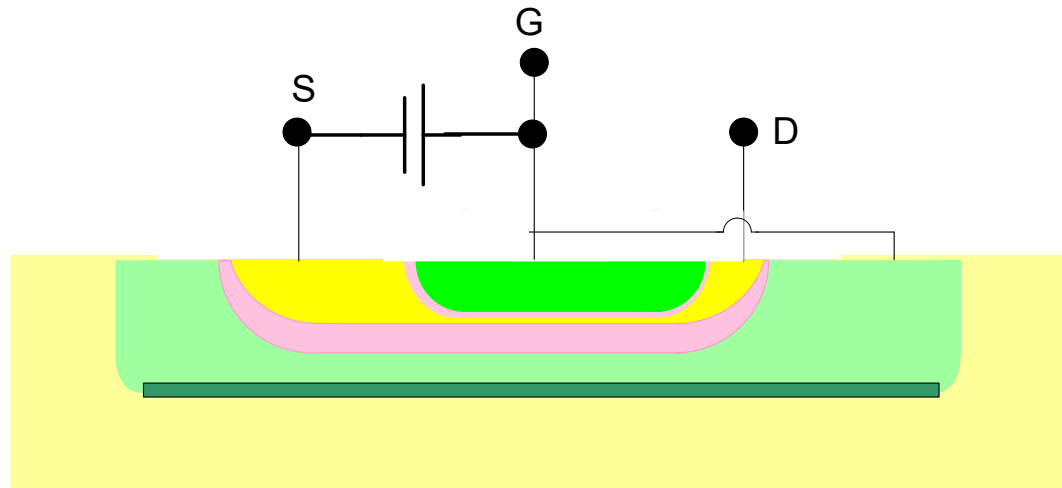


With $V_{GS}=0$, channel exists under gate between D and S

The JFET

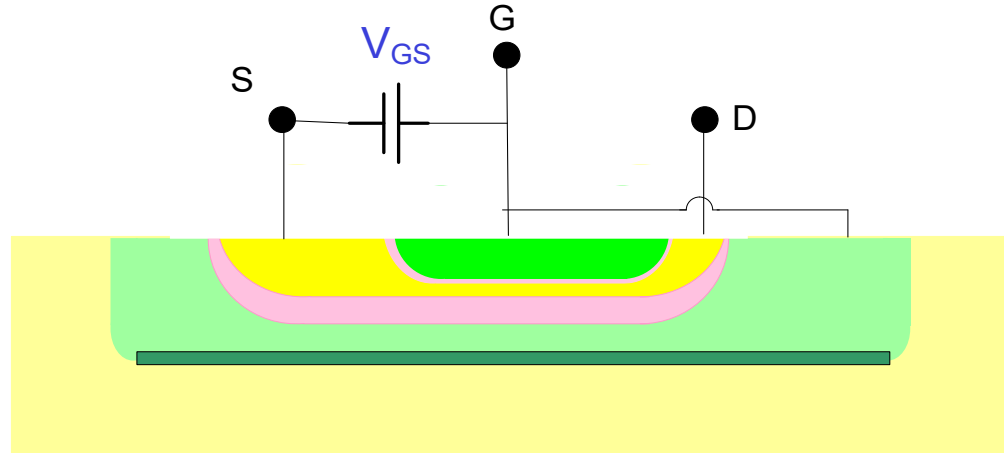


With $V_{GS}=0$, channel exists under gate between D and S

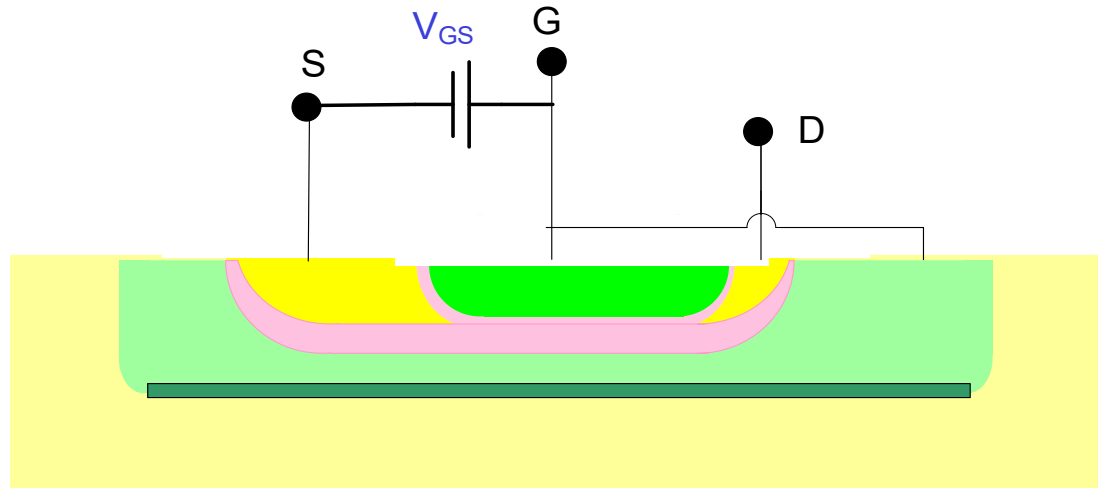


Under small reverse bias (depletion region widens and channel thins)

The JFET



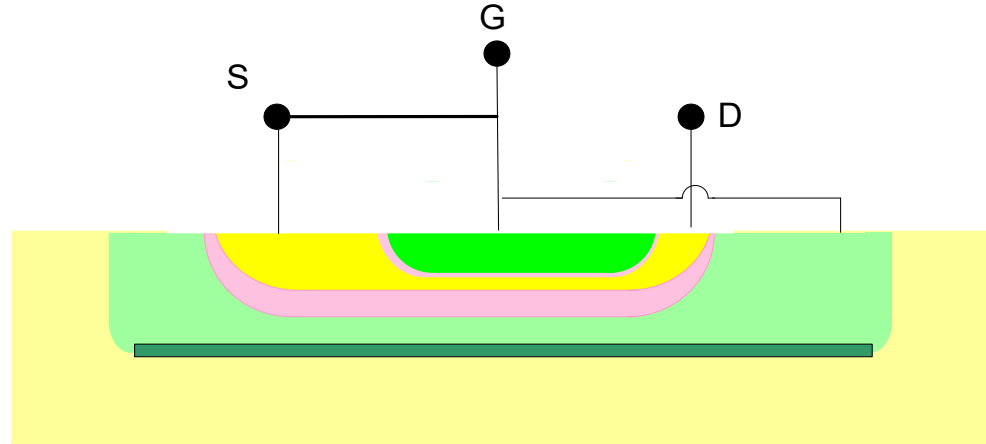
With $V_{GS}=0$, channel exists under gate between D and S



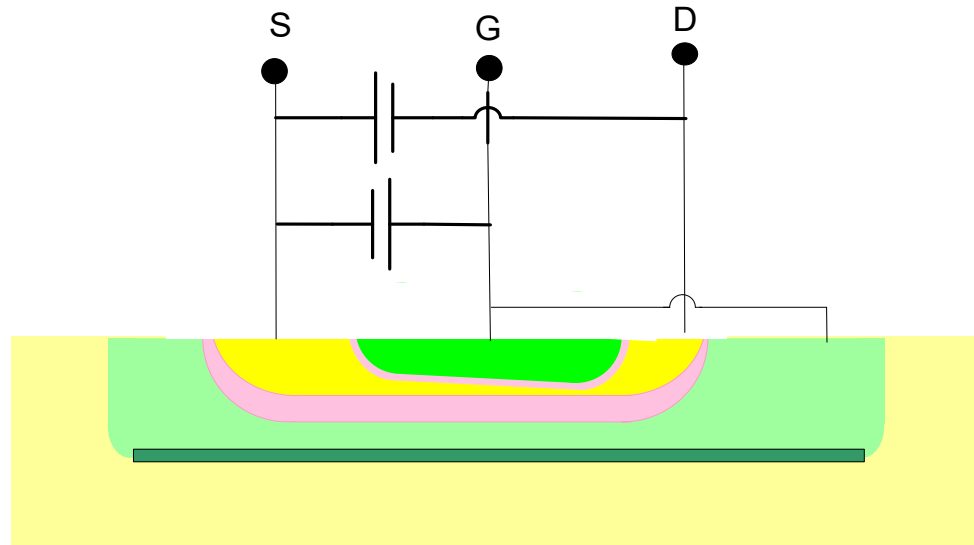
Under sufficiently large reverse bias (depletion region widens and channel disappears - "pinches off")

Value of V_{GS} that causes channel to "pinch off" termed the pinch-off voltage, $V_{GS, pinch}$

The JFET



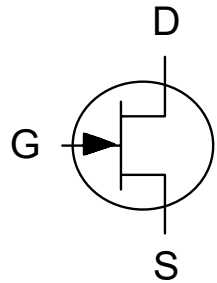
With $V_{GS} \leq V_P$ channel exists under gate between D and S



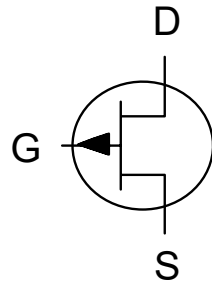
With $V_{GS} \leq V_P$ and sufficiently large negative V_{DS} , channel pinches off near drain

Electric field between gate and channel modulates the current flow in channel

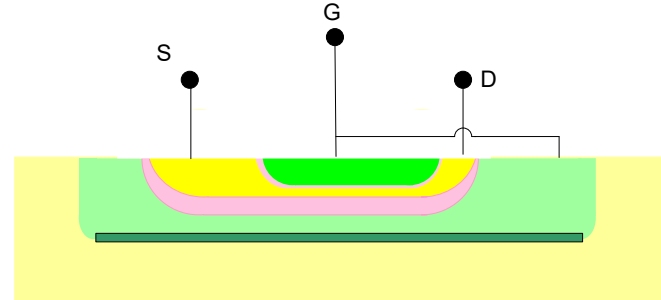
The JFET



n-channel



p-channel



p-channel JFET

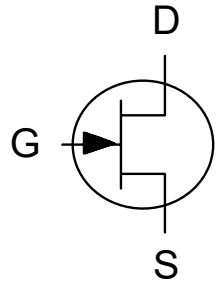
Square-law model of p-channel JFET

$$I_D = \begin{cases} 0 & V_{GS} > V_P \\ \frac{2I_{DSSp}}{V_P^2} \left(V_{GS} - V_P - \frac{V_{DS}}{2} \right) V_{DS} & -0.3 < V_{GS} < V_P \quad V_{GS} + 0.3 > V_{DS} > V_{GS} - V_P \\ I_{DSSp} \left(1 - \frac{V_{GS}}{V_P} \right)^2 & -0.3 < V_{GS} < V_P \quad V_{DS} < V_{GS} - V_P \end{cases}$$

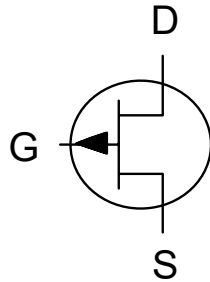
(I_{DSSp} carries negative sign)

- Functionally identical to the square-law model of MOSFET
- JFET is a depletion mode device
- Parameters I_{DSS} and V_P characterize the device
- I_{DSS} proportional to W/L where W and L are width and length of n+ diff
- V_P is negative for n-channel device, positive for p-channel device thus JFET is depletion mode device
- Must not forward bias GS junction by over about 300mV or excessive base current will flow (red constraint)
- Widely used as input stage for bipolar op amps

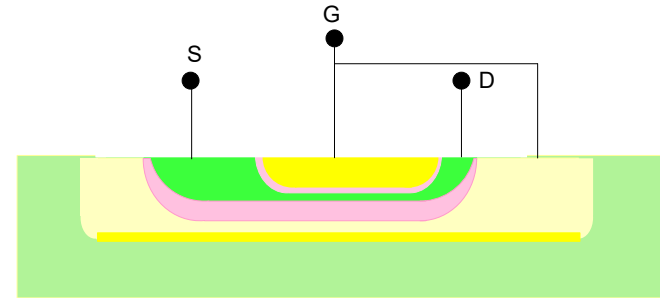
The JFET



n-channel



p-channel



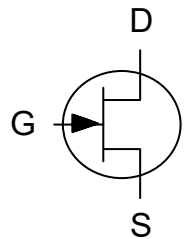
n-channel JFET
(not available in this process)

Square-law model of n-channel JFET

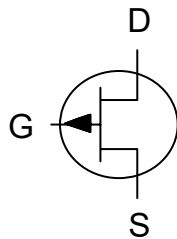
$$I_D = \begin{cases} 0 & V_{GS} < V_P \\ \frac{2I_{DSS}}{V_P^2} \left(V_{GS} - V_P - \frac{V_{DS}}{2} \right) V_{DS} & 0.3 > V_{GS} > V_P \quad V_{GS} - 0.3 < V_{DS} < V_{GS} - V_P \\ I_{DSS} \left(1 - \frac{V_{GS}}{V_P} \right)^2 & 0.3 > V_{GS} > V_P \quad V_{DS} > V_{GS} - V_P \end{cases}$$

- Functionally identical to the square-law model of MOSFET
- JFET is a depletion mode device
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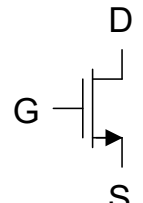
The FET Devices



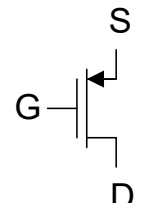
n-channel



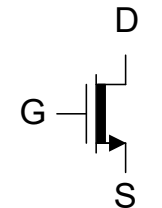
p-channel



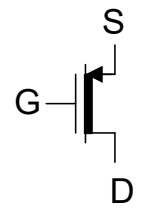
n-channel



p-channel



n-channel



p-channel

$$I_D = \begin{cases} 0 & \text{cutoff} \\ \frac{2I_{DSS}}{V_P^2} \left(V_{GS} - V_P - \frac{V_{DS}}{2} \right) V_{DS} & \text{Triode} \\ I_{DS} \left(1 - \frac{V_{GS}}{V_P} \right)^2 & \text{Saturation} \end{cases}$$

$$I_D = \begin{cases} 0 & \text{Cutoff} \\ \frac{\mu C_{OX} W}{L} \left(V_{GS} - V_{TH} - \frac{V_{DS}}{2} \right) V_{DS} & \text{Triode} \\ \frac{\mu C_{OX} W}{2L} (V_{GS} - V_{TH})^2 & \text{Saturation} \end{cases}$$

I_{DSS} proportional to W/L where W and L are width and length of n+ diff (could define $I_{DSS} = \hat{I}_{DSS} \frac{W}{L}$)

V_P and V_{TH} are analogous

$\frac{2\hat{I}_{DSS}}{V_P^2}$ and μC_{OX} are analogous

Basic circuit structures are the same (with different biasing implications)

Outline

Bipolar Processes

- Parasitic Devices in CMOS Processes
- JFET

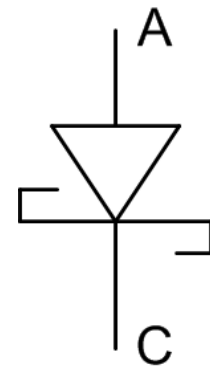
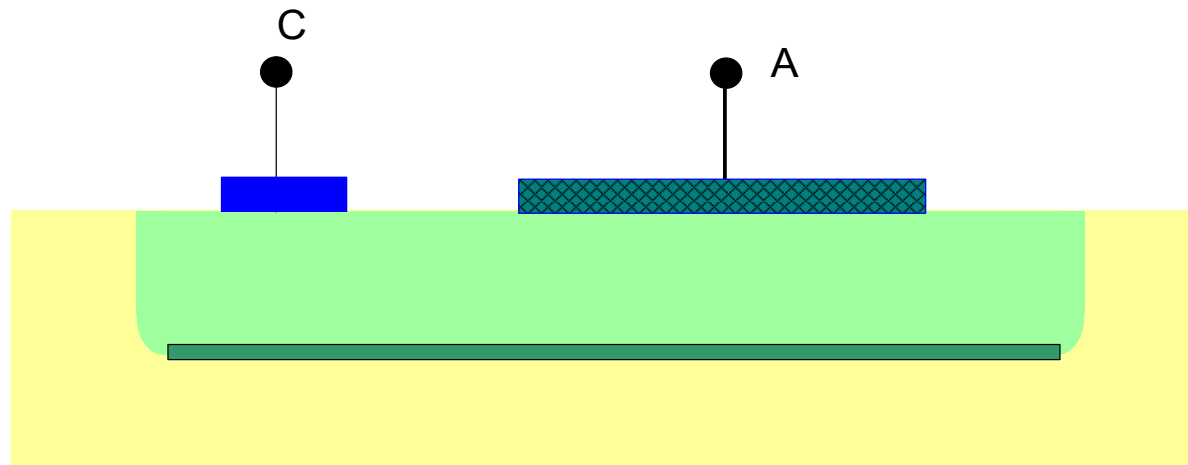


Other Junction Devices

Special Bipolar Processes

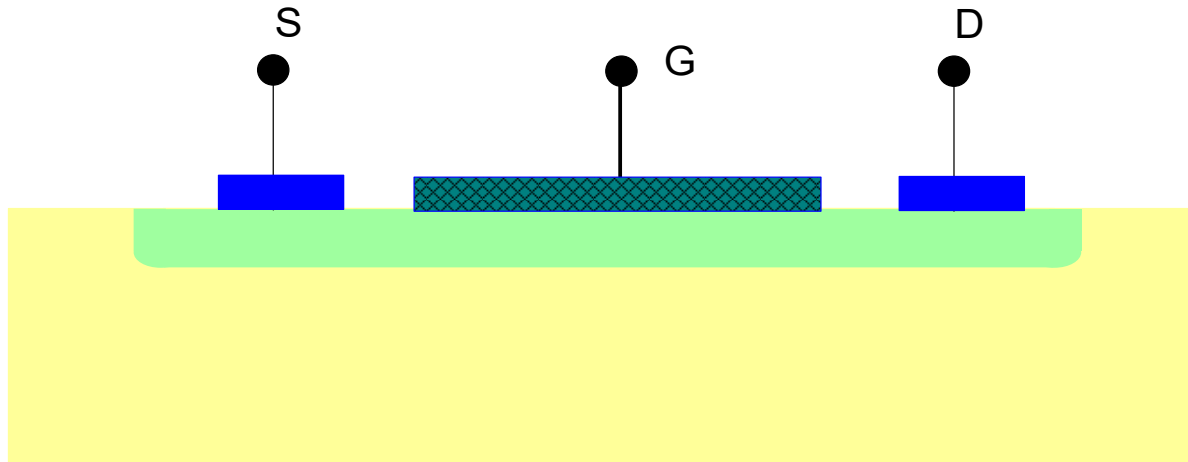
- Thyristors
SCR
TRIAC

The Schottky Diode



- Metal-Semiconductor Junction
- One contact is ohmic, other is rectifying
- Not available in all processes
- Relatively inexpensive adder in some processes
- Lower cut-in voltage than pn junction diode
- High speed

The MESFET

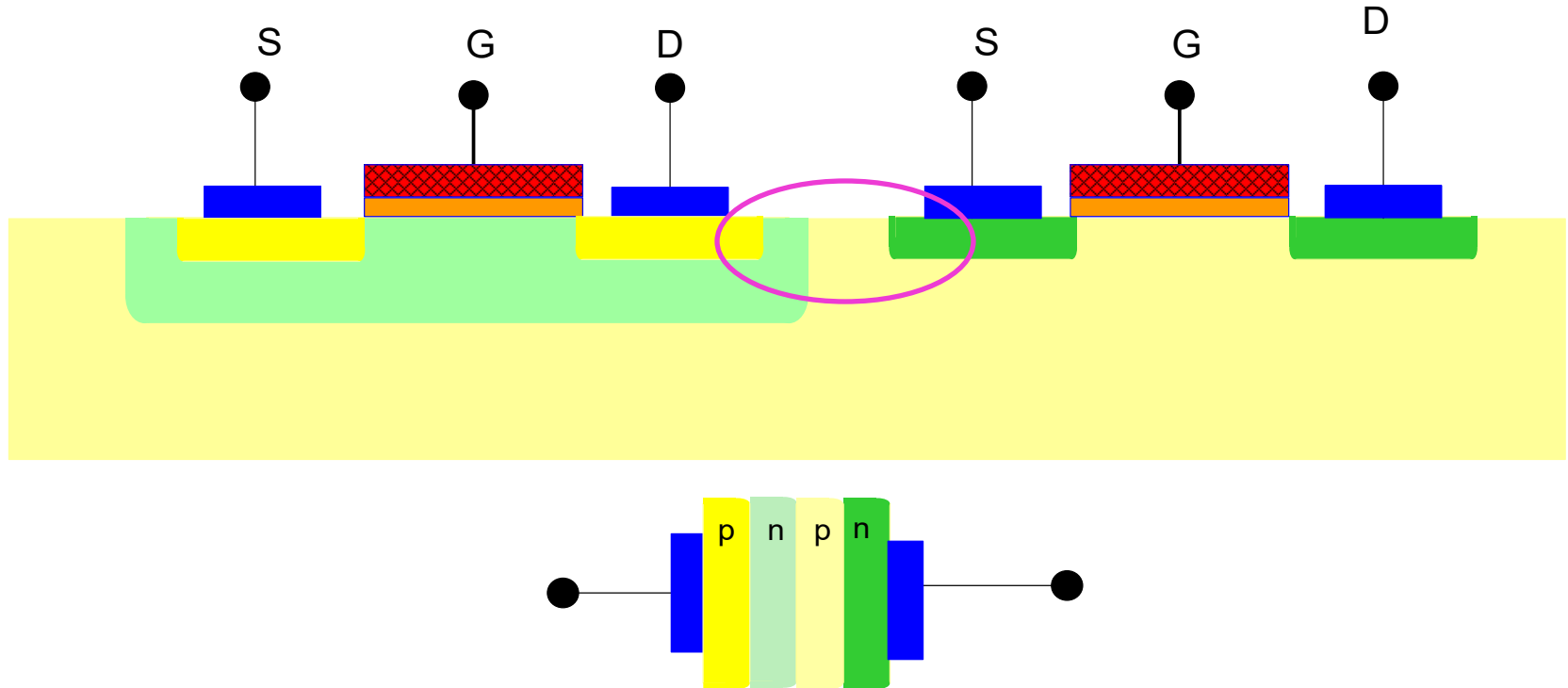


- Metal-Semiconductor Junction for Gate
- Drain and Source contacts ohmic, other is rectifying
- Usually not available in standard CMOS processes
- Must not forward bias very much
- Lower cut-in voltage than pn junction diode
- High speed

The Thyristor

A bipolar device in CMOS Processes

Consider a Bulk-CMOS Process



Have formed a lateral pnpn device !

Will spend some time studying pnpn devices

Outline

Bipolar Processes

- Parasitic Devices in CMOS Processes
- JFET
- Other Junction Devices

Special Bipolar Processes



Thyristors

SCR

TRIAC

Thyristors

The good and the bad!

Thyristors

The good

SCRs

Triacs

The bad

Parasitic Device that can destroy integrated circuits

Outline

Bipolar Processes

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Special Bipolar Processes

- Thyristors



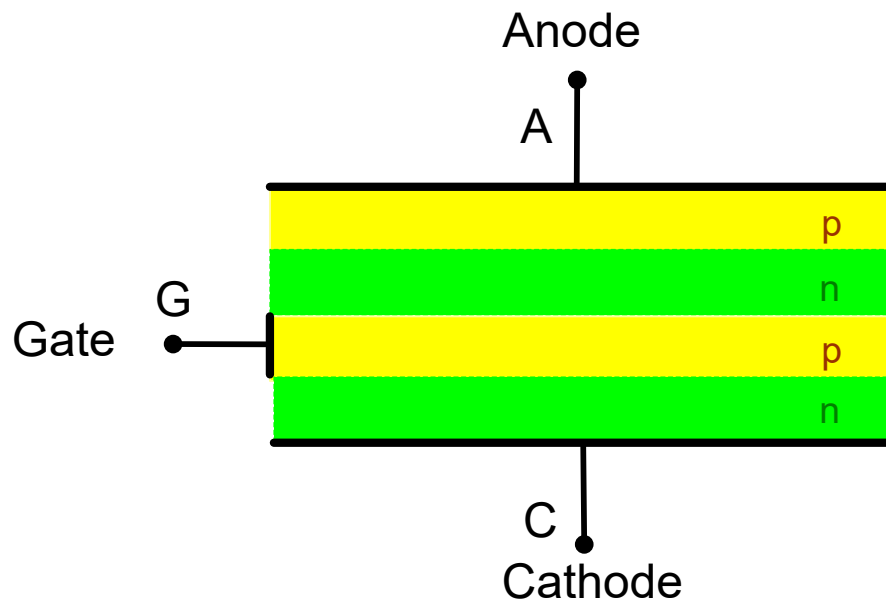
SCR

TRIAC

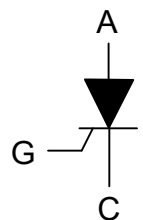
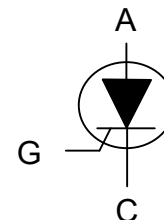
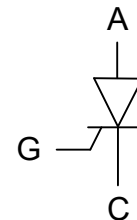
The SCR

Silicon Controlled Rectifier

- Widely used to switch large resistive or inductive loads
- Widely used in the power electronics field
- Widely used in consumer electronic to interface between logic and power



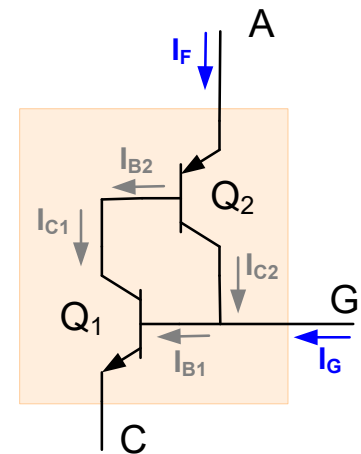
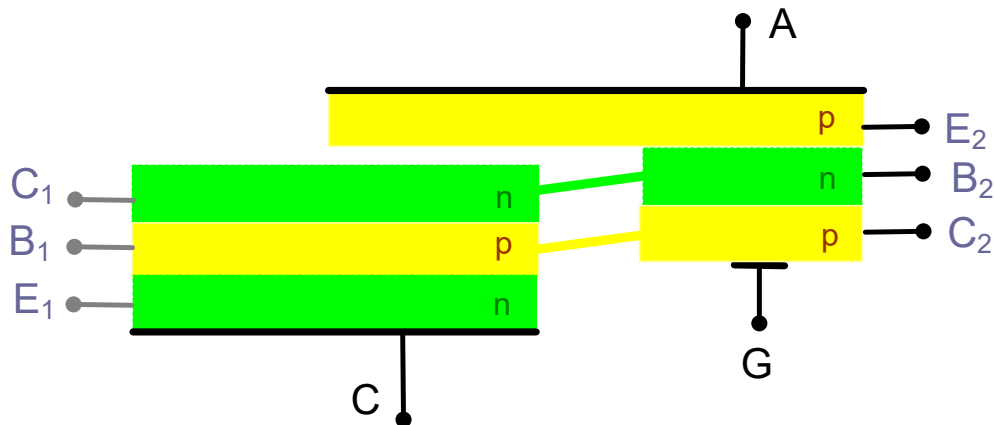
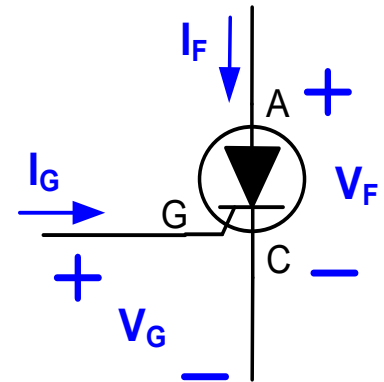
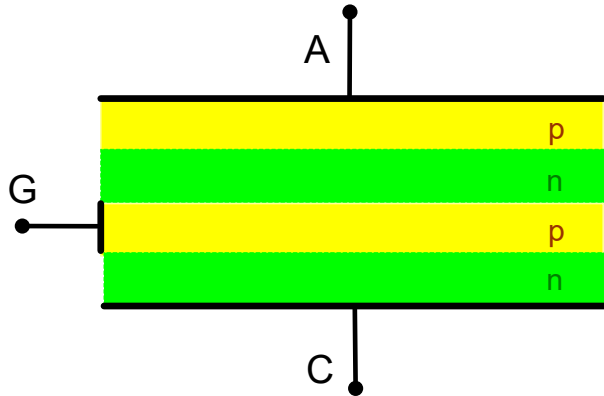
Usually made by diffusions in silicon



Symbols

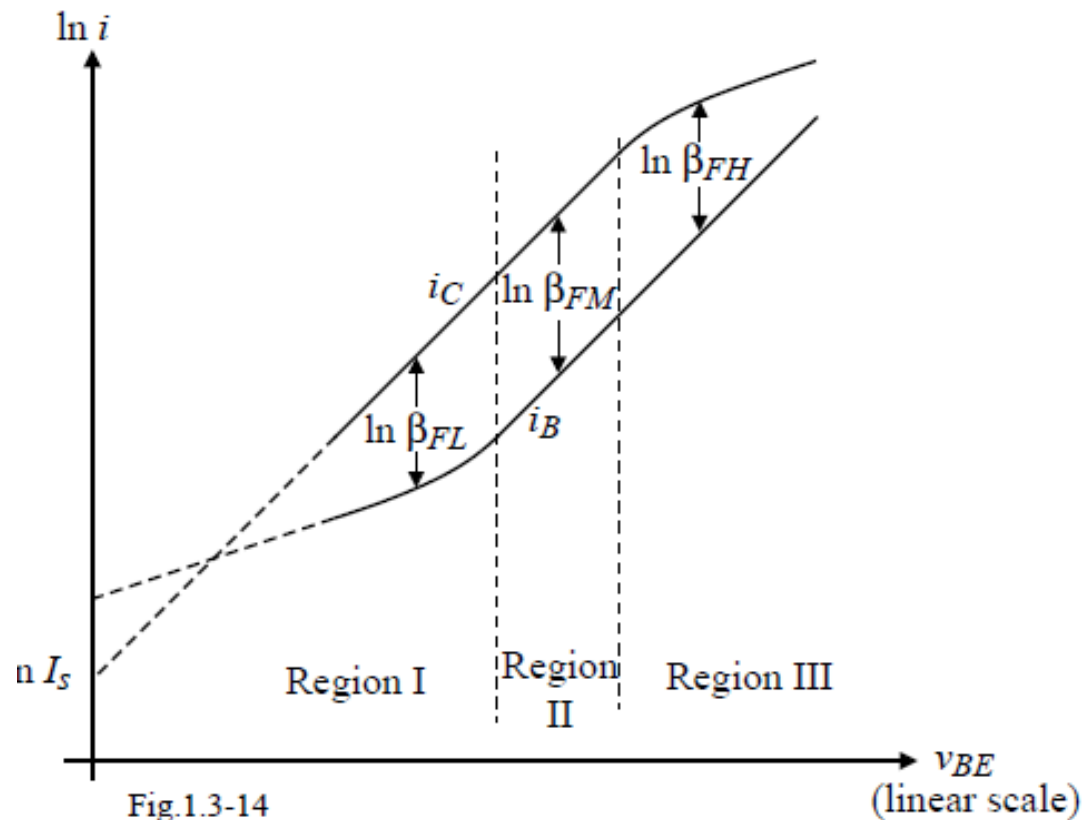
Consider first how this 4-layer 3-junction device operates

Operation of the SCR



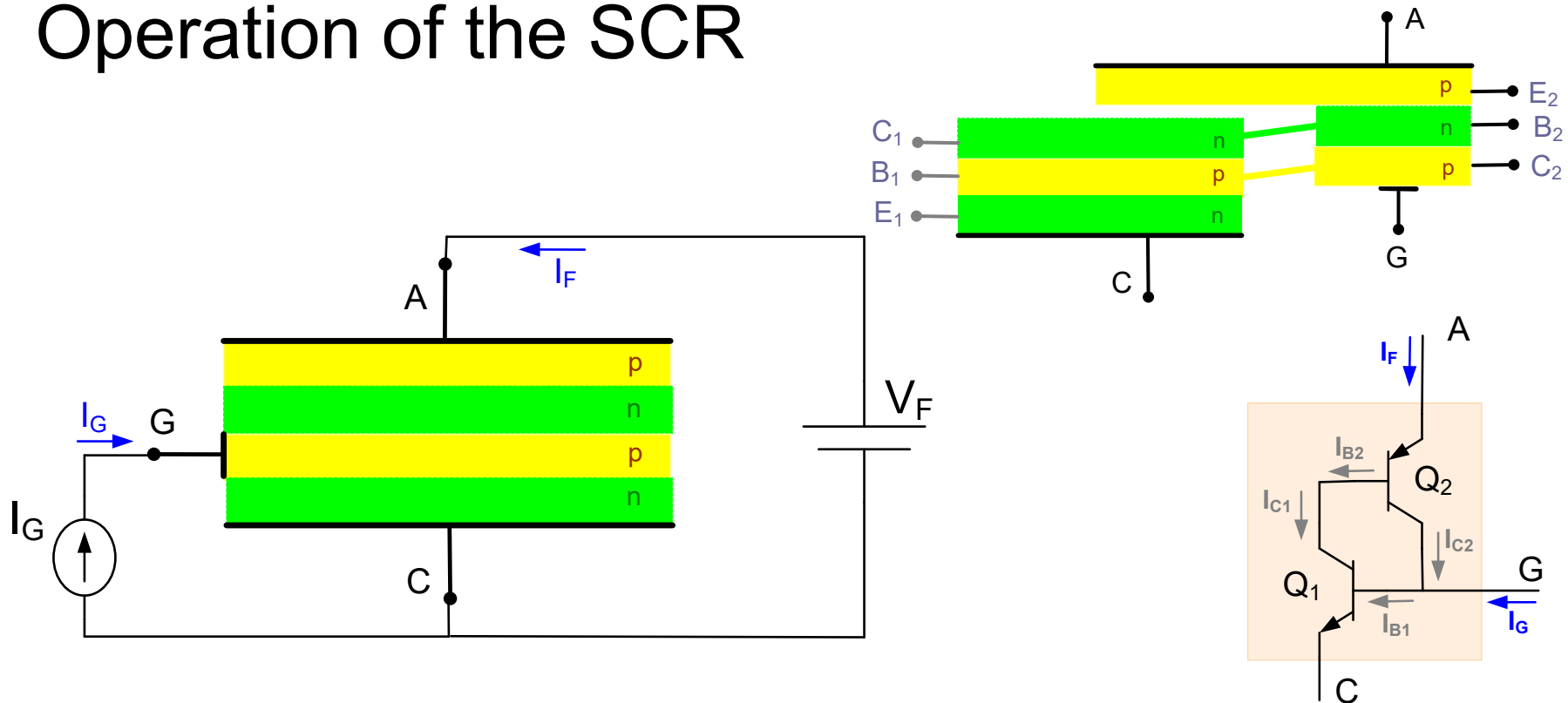
Not actually separated but useful for describing operation

Variation of Current Gain (β) with Bias for BJT



Note that current gain gets very small at low base current levels

Operation of the SCR



Consider a small positive bias (voltage or current) on the gate ($V_{GC} < 0.5V$) and a positive and large voltage V_F

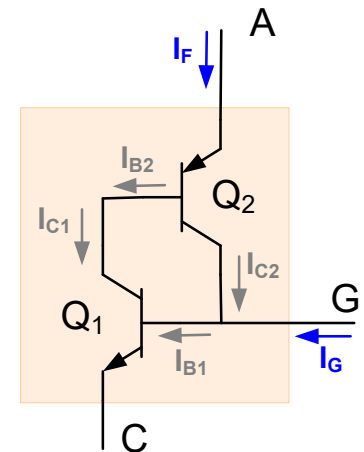
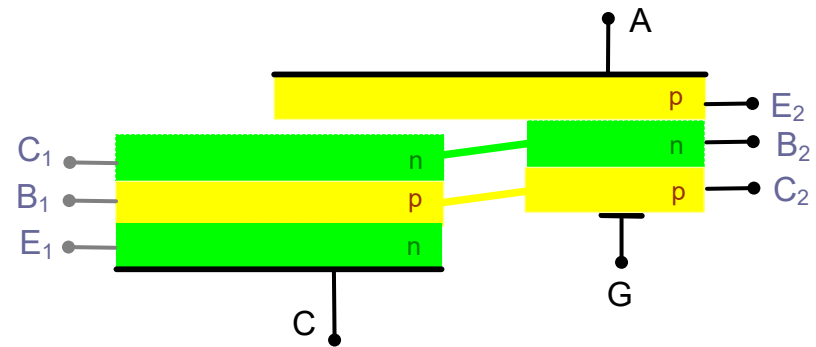
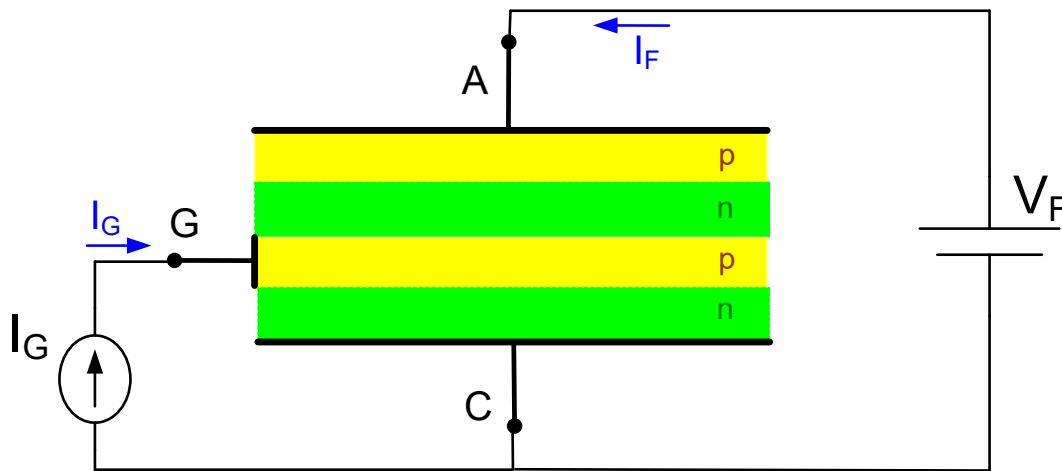
Will have $V_{C1} \geq V_F - 0.5V$

Thus Q_1 has a large positive voltage on its collector

Since V_{BE1} is small, I_{C1} will be small as will I_{C2} , diode equation governs BE junction of Q_1

I_F will be very small

Operation of the SCR



Now let bias on the gate increase (V_{GC} around 0.6V) so Q_1 and Q_2 in FA $V_{C1} \geq V_F - 0.5V$

From diode equation, base voltage V_{BE1} will increase and collector current I_{C1} will increase

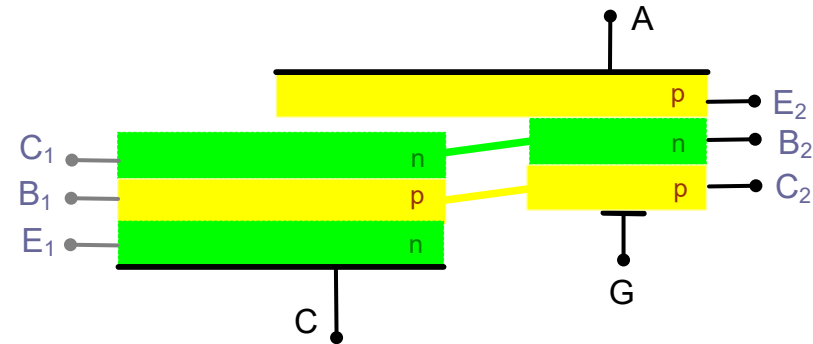
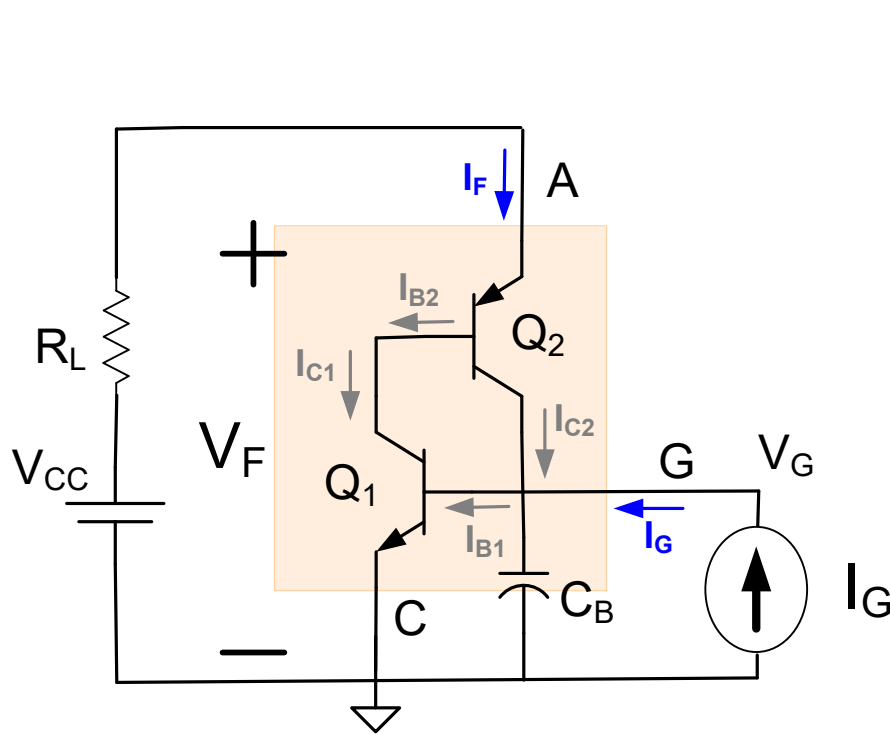
Thus base current I_{B2} will increase as will the collector current of I_{C2}

Under assumption of operation in FA region get expression

$$I_{B1} = I_G + \beta_1 \beta_2 I_{B1}$$

This is regenerative feedback (actually can show pole in RHP) 39 of 71 Slides

Very Approximate Analysis Showing RHP Pole



$$V_G = I_G \frac{R_{BE}}{sR_{BE}C_B + 1 - \beta_1\beta_2}$$

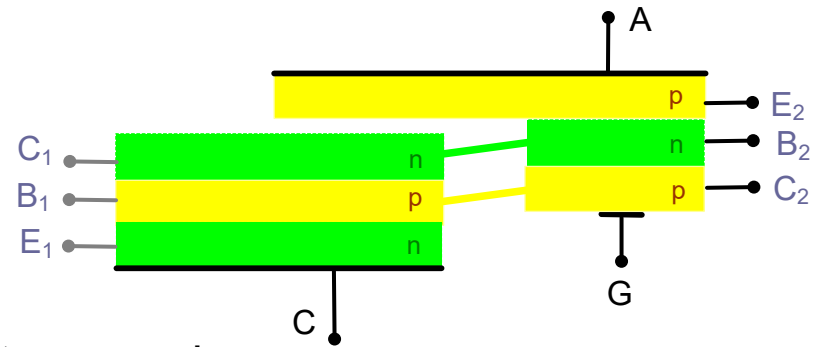
$$V_G s C_B + I_{B1} = I_{C2} + I_G$$

$$I_{C2} = \beta_1 \beta_2 I_{B1}$$

$$I_{B1} R_{BE} = V_G$$

$$p = \frac{\beta_1 \beta_2 - 1}{R_{BE} C_B}$$

Operation of the SCR



$$V_{C1} \cong V_F - 0.6V$$

Under assumption of operation in FA region get expression

$$I_{B1} = I_G + \beta_1 \beta_2 I_{B1}$$

What will happen with this is regenerative feedback?

If I_G is small (and thus β_1 and β_2 are small) I_F will be very small

If I_G larger (and $\beta_1 \beta_2 I_{B1} > I_G$), I_G can be removed and current will continue to flow

I_{C1} will continue to increase and drive Q_1 into SAT

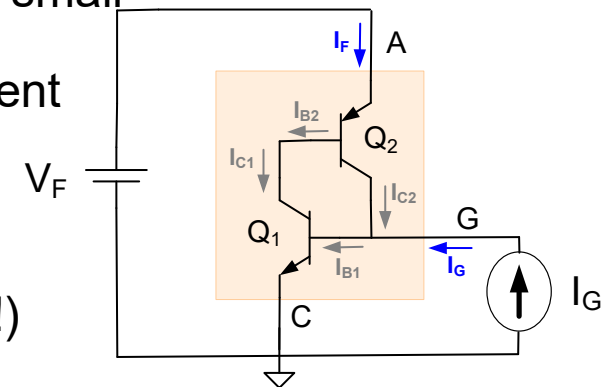
This will try to drive V_A towards 0.9V (but forced to be V_F !)

The current in V_F will go towards ∞

The SCR will self-destruct because of excessive heating !

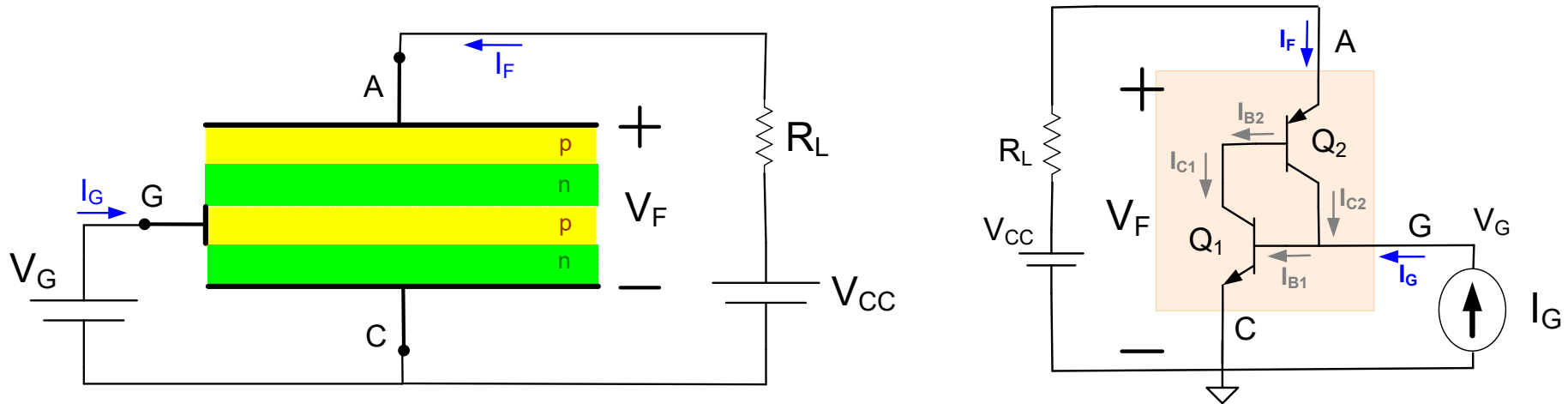


Too bad the circuit self-destructed because the small gate current was able to control a lot of current!



Operation of the SCR

Consider a modified application by adding a load (depicted as R_L)



All operation is as before, but now, after the triggering occurs, the voltage V_F will drop to approximately 0.8 V and the voltage $V_{CC} - 0.8$ will appear across R_L

If V_{CC} is very large, the SCR has effectively served as a switch putting V_{CC} across the load and after triggering occurs, I_G can be removed!

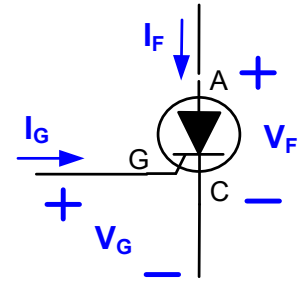
But, how can we turn it off?

Will discuss that later

Operation of the SCR

SCR model

$$\left. \begin{aligned} I_F &= f_1(V_F, V_G) \\ I_G &= f_2(V_G) \end{aligned} \right\}$$



As for MOSFET, Diode, and BJT, several models for SCR can be developed

The Ideal SCR Model

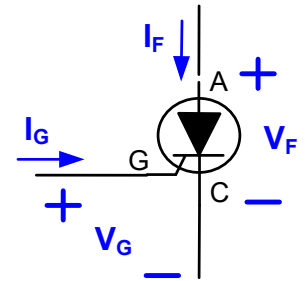
$$\left. \begin{aligned} I_F &= f_{1I}(V_F, I_G) \\ I_G &= f_{2I}(V_G) \end{aligned} \right\}$$

or

$$\left. \begin{aligned} I_F &= f_{1IA}(V_F, V_G) \\ I_G &= f_{2I}(V_G) \end{aligned} \right\}$$

Operation of the SCR

Consider the Ideal SCR Model



$$\left. \begin{aligned} I_F &= f_{1I}(V_F, I_G) \\ I_G &= f_{2I}(V_F) \end{aligned} \right\}$$

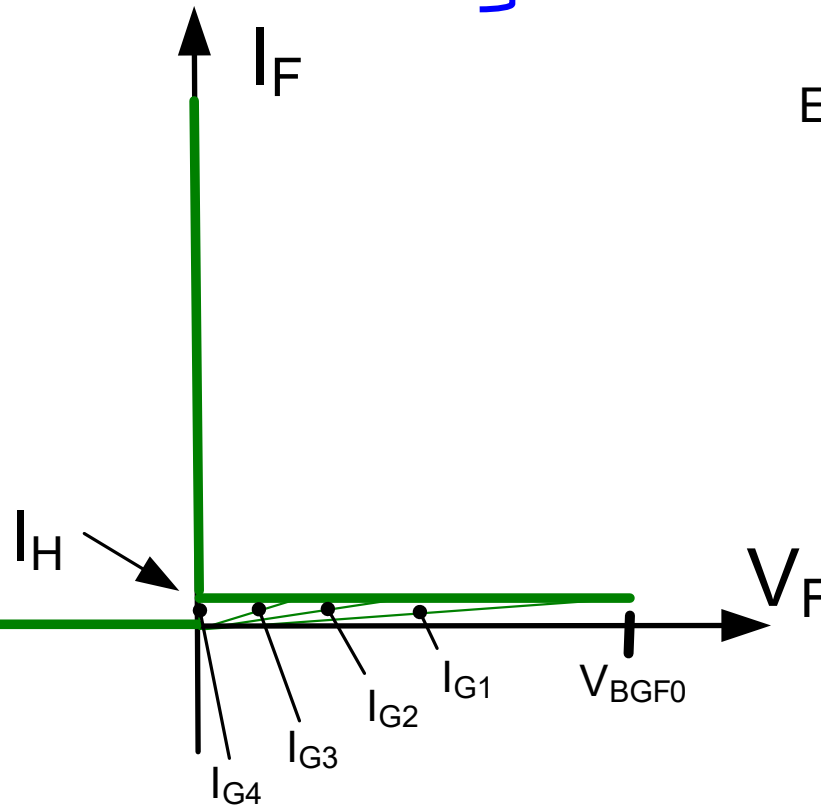
Empirical Model

$$V_F = 0 \quad \text{if} \quad I_F > I_H$$

$$V_F = \frac{\theta}{I_G} I_F \quad \text{if} \quad 0 < I_F < I_H$$

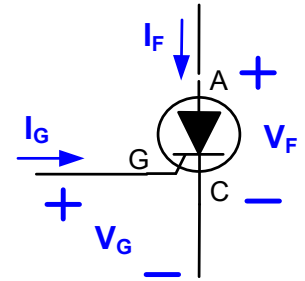
$$I_F = 0 \quad \text{if} \quad V_F < 0$$

I_H is very small
 V_{BGF0} very large

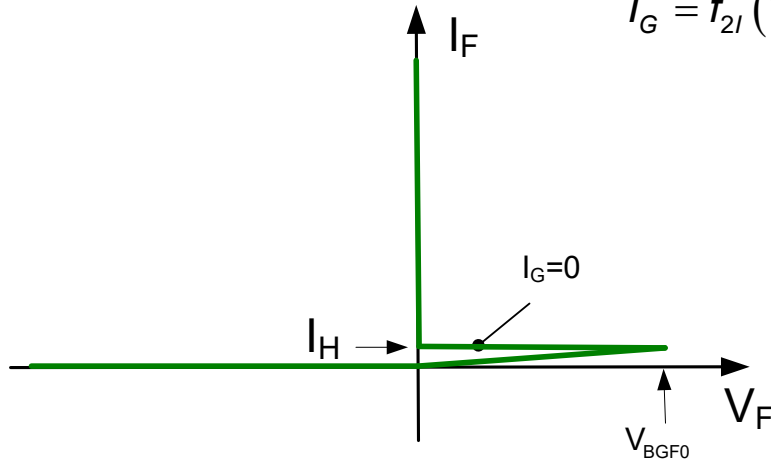


Operation of the SCR

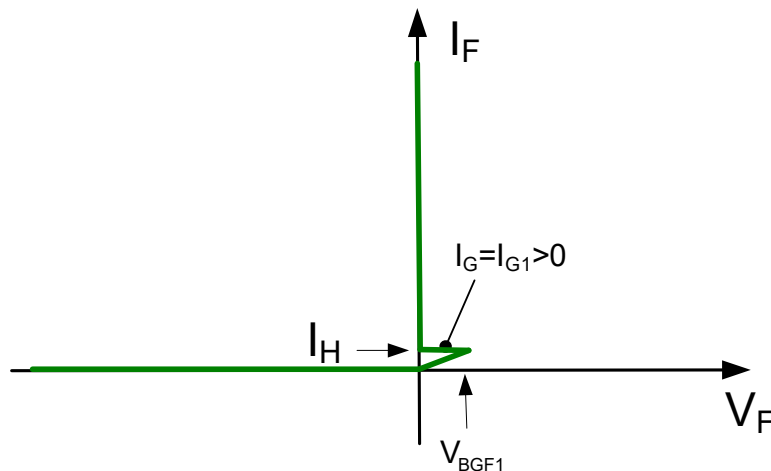
Consider the Ideal SCR Model



$$\left. \begin{aligned} I_F &= f_{1I}(V_F, I_G) \\ I_G &= f_{2I}(V_G) \end{aligned} \right\}$$



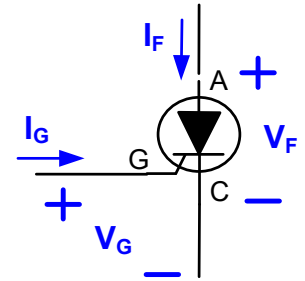
I_H is very small
 V_{BGF0} very large



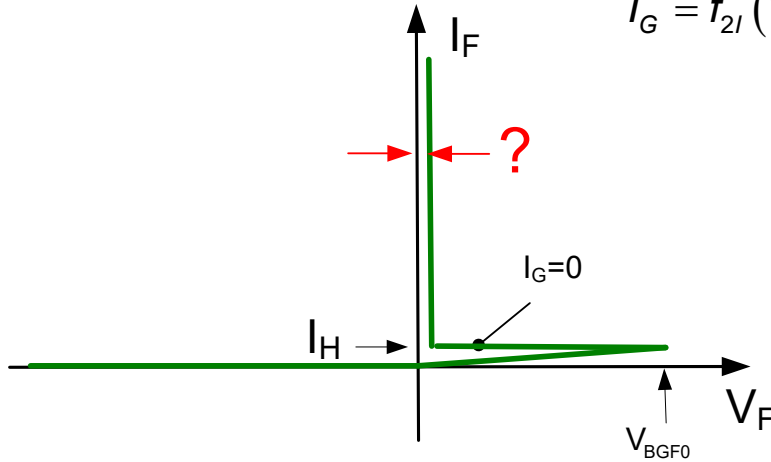
I_{G1} is small (but not too small)
 V_{BGF1} very small

Operation of the SCR

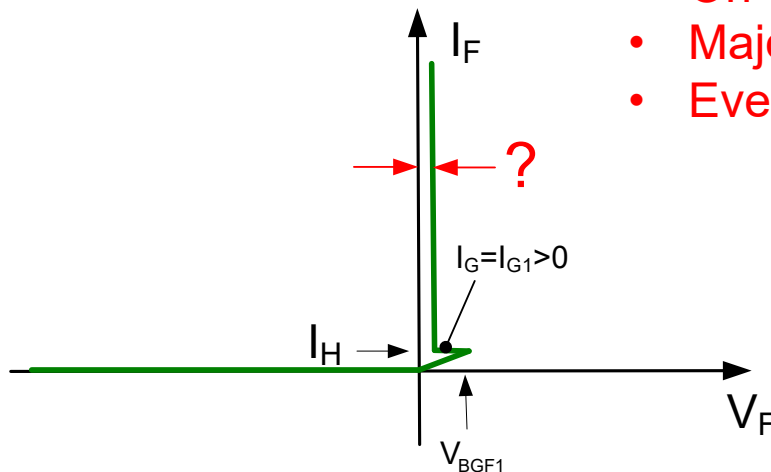
Consider nearly Ideal SCR Model



$$\left. \begin{aligned} I_F &= f_{1I}(V_F, I_G) \\ I_G &= f_{2I}(V_F) \end{aligned} \right\}$$



- On voltage approximately 0.9V
- Major contributor to ON-state power dissipation
- Even with large currents, P_{ON} is quite small



Operation of the SCR

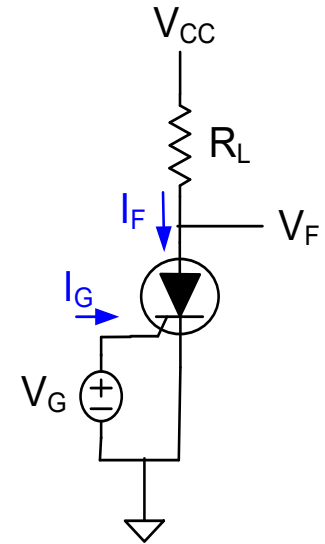
Operation with the Ideal SCR

Load Line: $V_{CC} = I_F R_L + V_F$

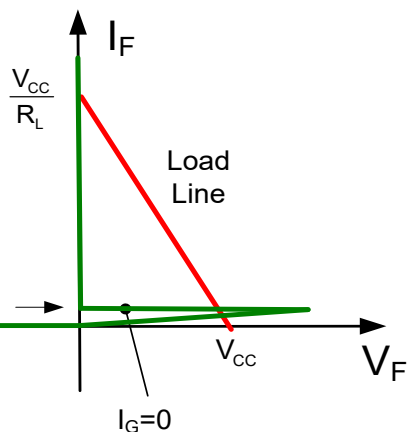
Analysis: $V_{CC} = I_F R_L + V_F$
 $I_F = f_{1I}(V_F, V_G)$

$$I_F = f_1(V_F, V_G)$$

$$I_G = f_2(V_G)$$



The solution of these two equations is at the intersection of the load line and the device characteristics



when $I_G = 0$

Note three intersection points

Two (upper and lower) are stable equilibrium points, one is not

When operating at any upper point, $V_F = 0$ so V_{CC} appears across R_L . We say SCR is ON

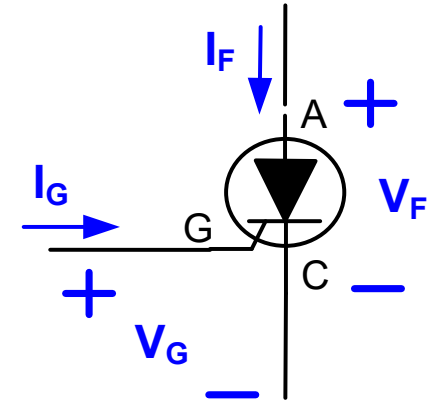
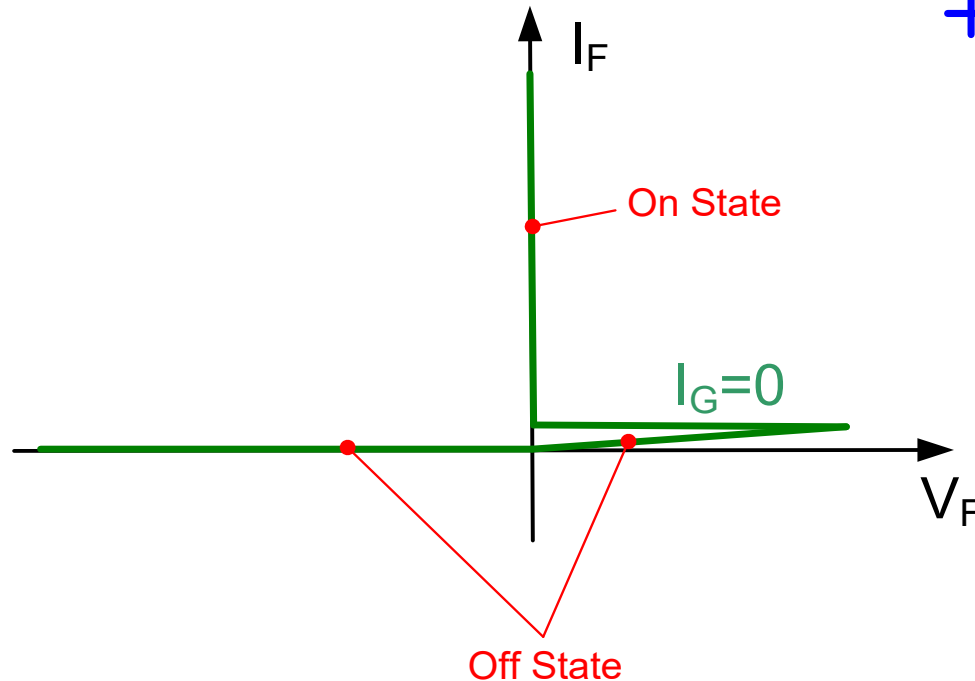
When operating at any lower point, I_F approx 0 so no signal across R_L . We say SCR is OFF

When $I_G = 0$, will stay in whatever state it was in

Operation of the SCR

Operation with the Ideal SCR

$$I_F = f_{11}(V_F, I_G)$$



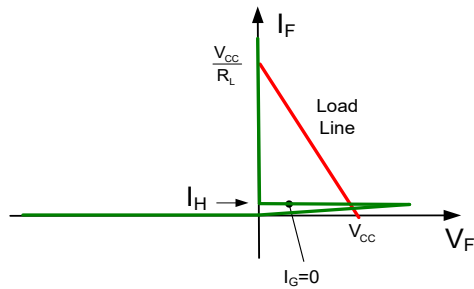
For notational convenience will drop subscript unless emphasis is needed

$$I_F = f_{11}(V_F, I_G) \quad \longrightarrow \quad I_F = f(V_F, I_G)$$

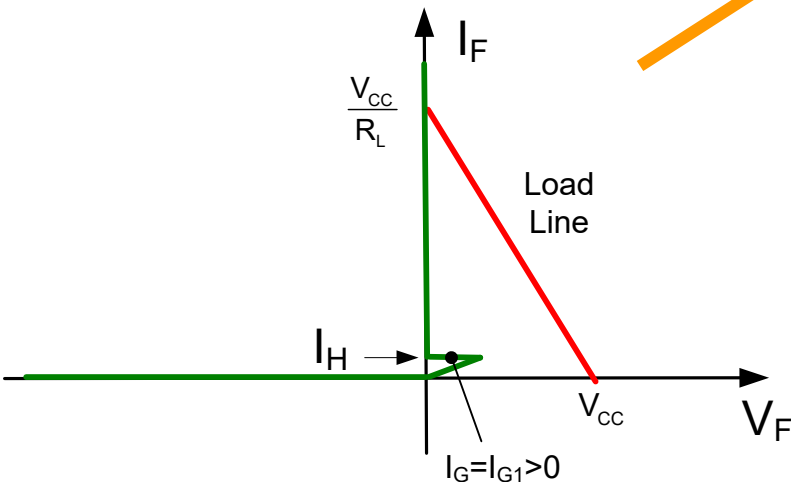
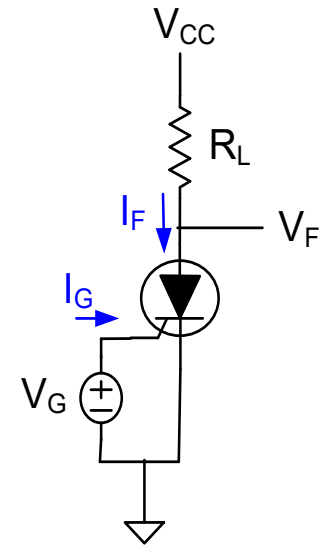
Operation of the SCR

Operation with the Ideal SCR

Now assume it was initially in the OFF state and then a gate current was applied



$$\left. \begin{aligned} V_{CC} &= I_F R_L + V_F \\ I_F &= f(V_F, I_G) \end{aligned} \right\}$$



Now there is a single intersection point so a unique solution

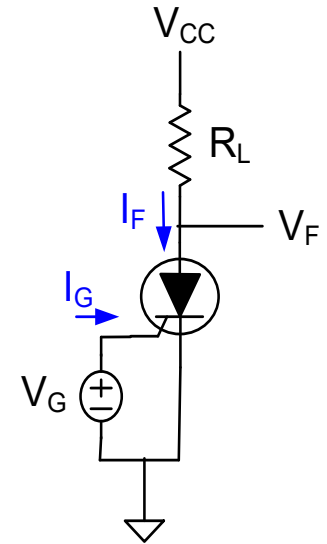
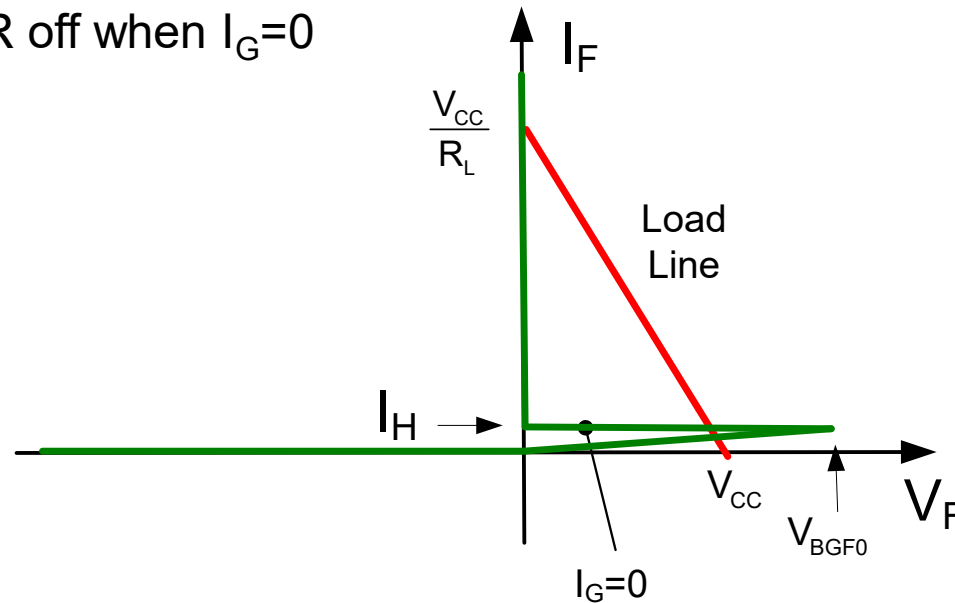
The SCR is now ON

Removing the gate current will return to the previous solution (which has 3 intersection points) but it will remain in the ON state

Operation of the SCR

Operation with the Ideal SCR

Turning SCR off when $I_G = 0$



Reduce V_{CC} so that V_{CC}/R_L goes below I_H

This will provide a single intersection point

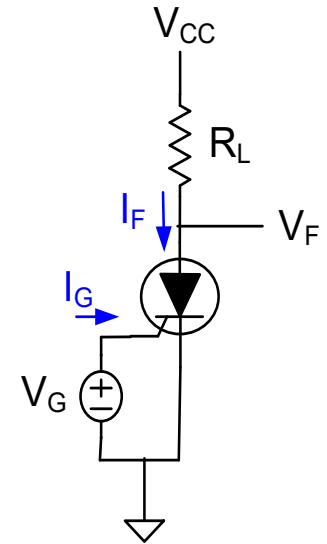
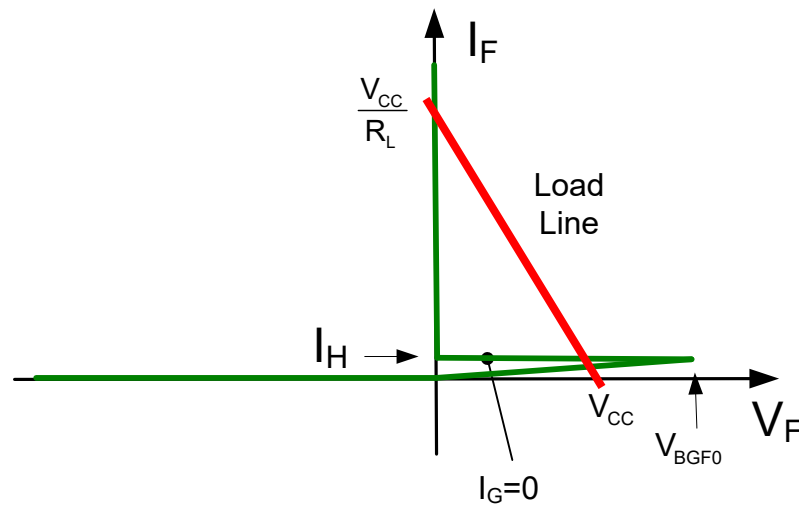
V_{CC} can then be increased again and SCR will stay off

Must not increase V_{CC} much above V_{BGF0} else will turn on

Operation of the SCR

Operation with the Ideal SCR

Turning SCR off when $I_G=0$

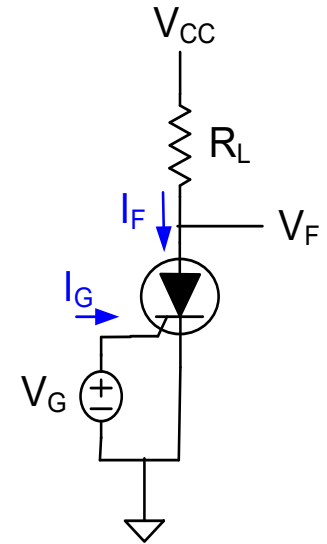
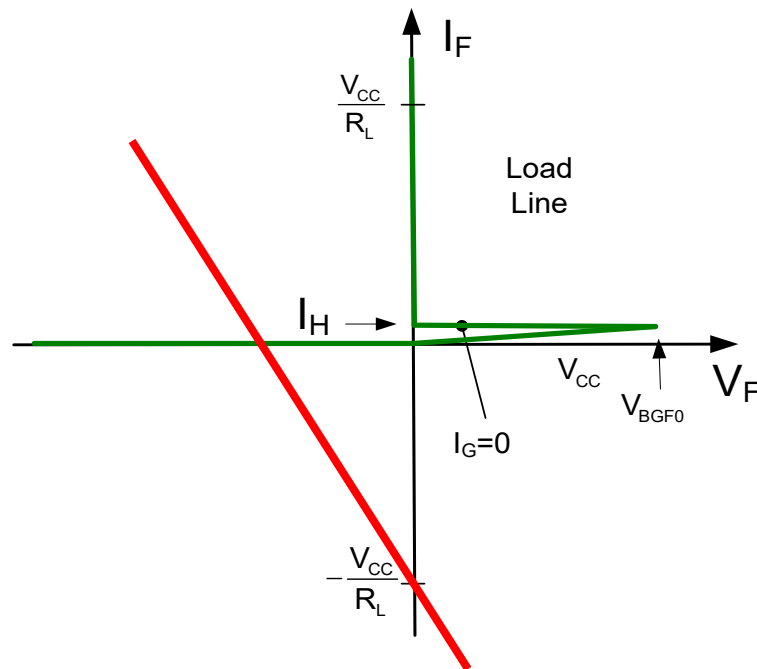


Operation of the SCR

Operation with the Ideal SCR

Often V_{CC} is an AC signal (often 110V)

SCR will turn off whenever AC signal goes negative

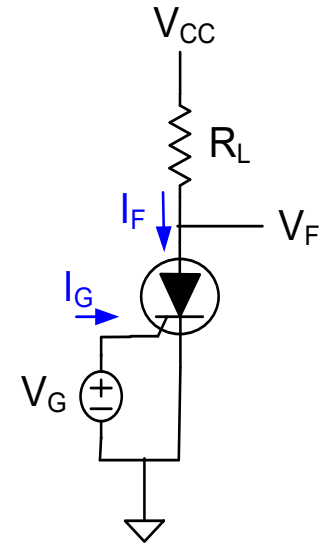
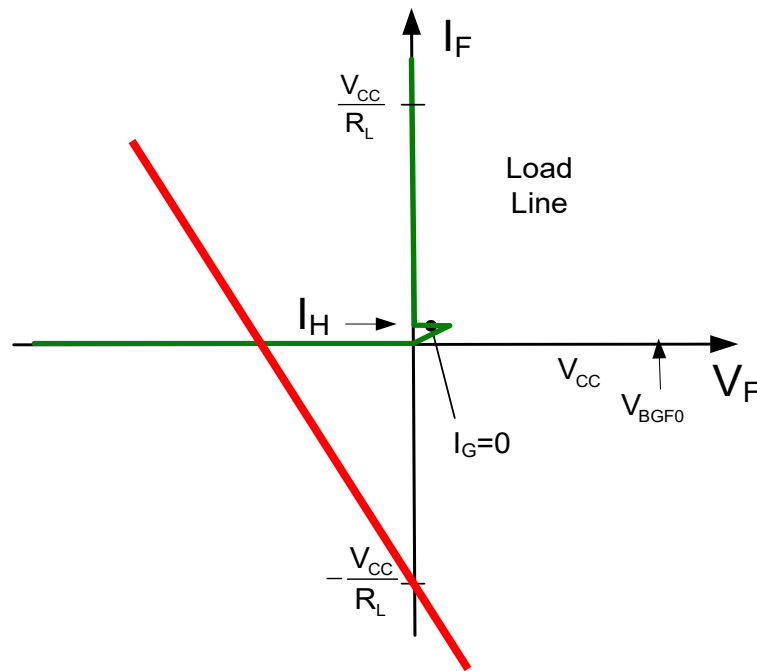


Operation of the SCR

Operation with the Ideal SCR

Often V_{CC} is an AC signal (often 110V)

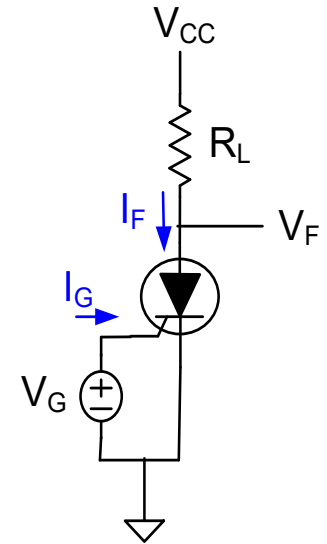
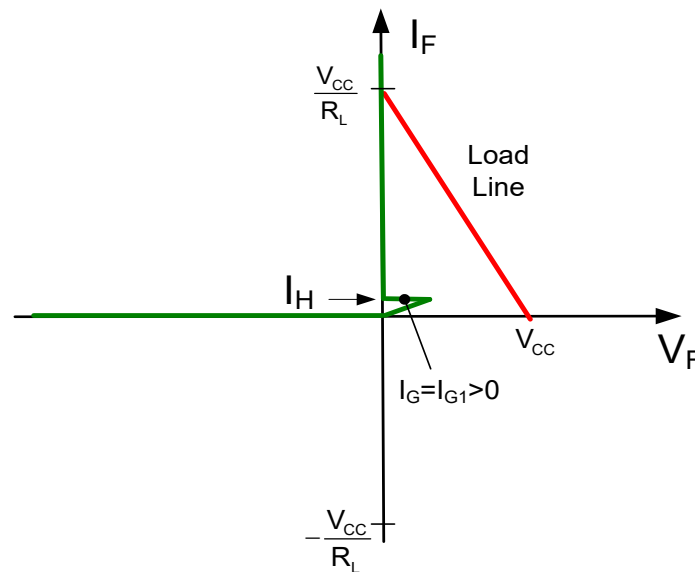
SCR will turn off whenever AC signal goes negative



Operation of the SCR

Operation with the Ideal SCR

Turning SCR off when $I_G > 0$



Reduce V_{CC} so that V_{CC}/R_L goes below I_H

This will provide a single intersection point

But when V_{CC} is then increased SCR will again turn on



Stay Safe and Stay Healthy !

End of Lecture 29